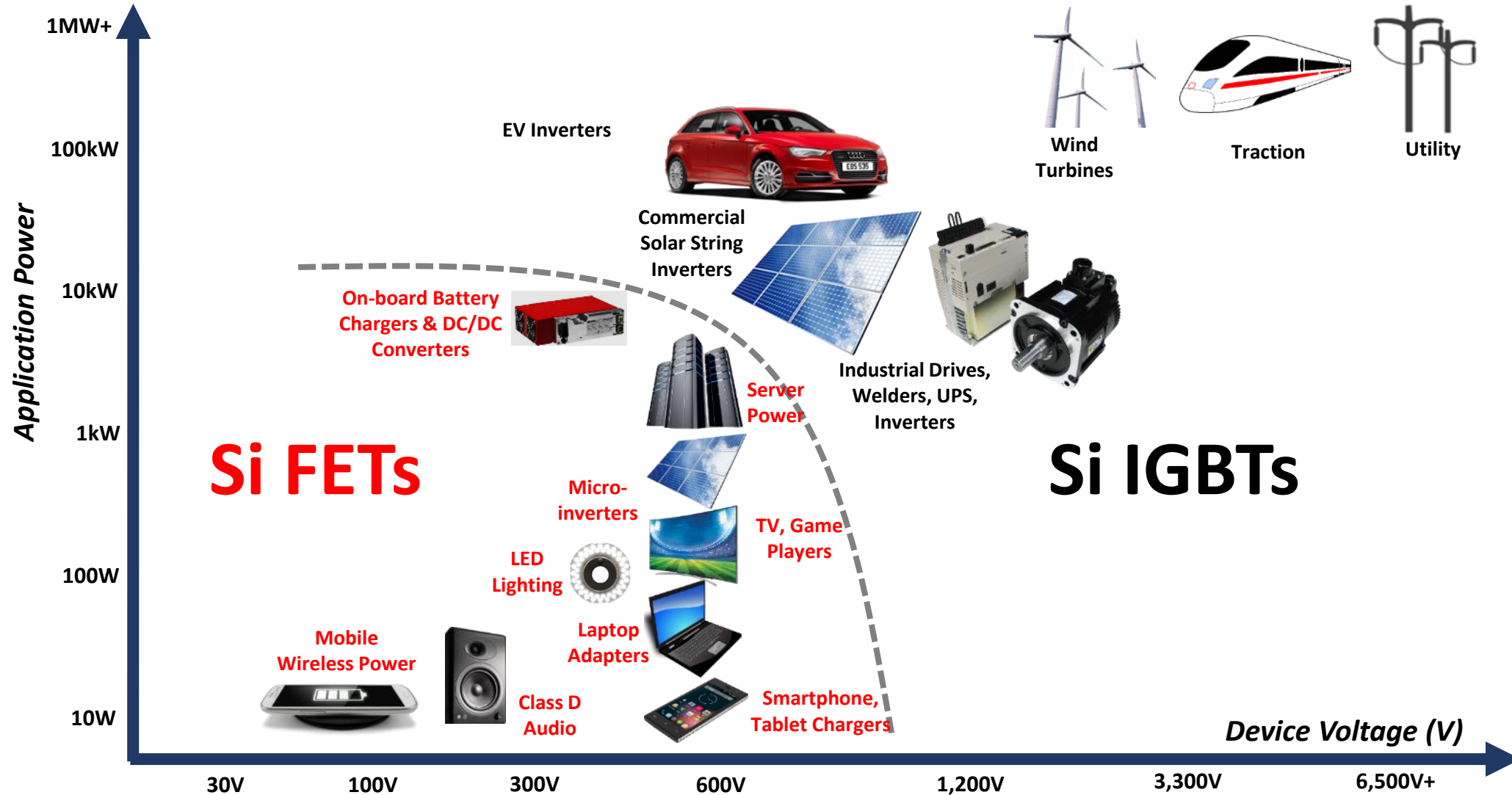


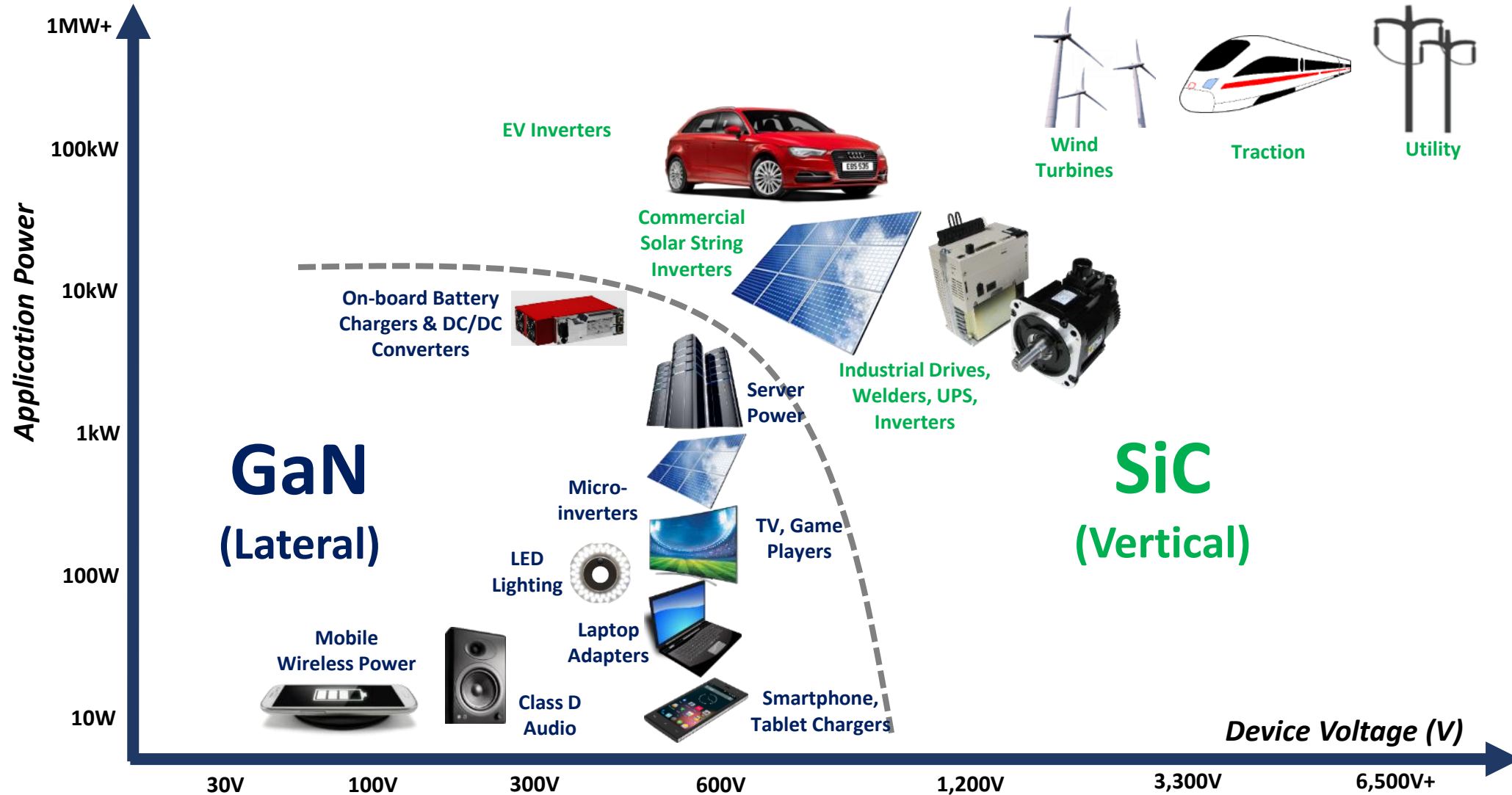
**DRIVING FOR ZERO SWITCHING LOSS  
POWER SOLUTIONS**

**Dan Kinzer, CTO**  
June 28<sup>th</sup> 2016

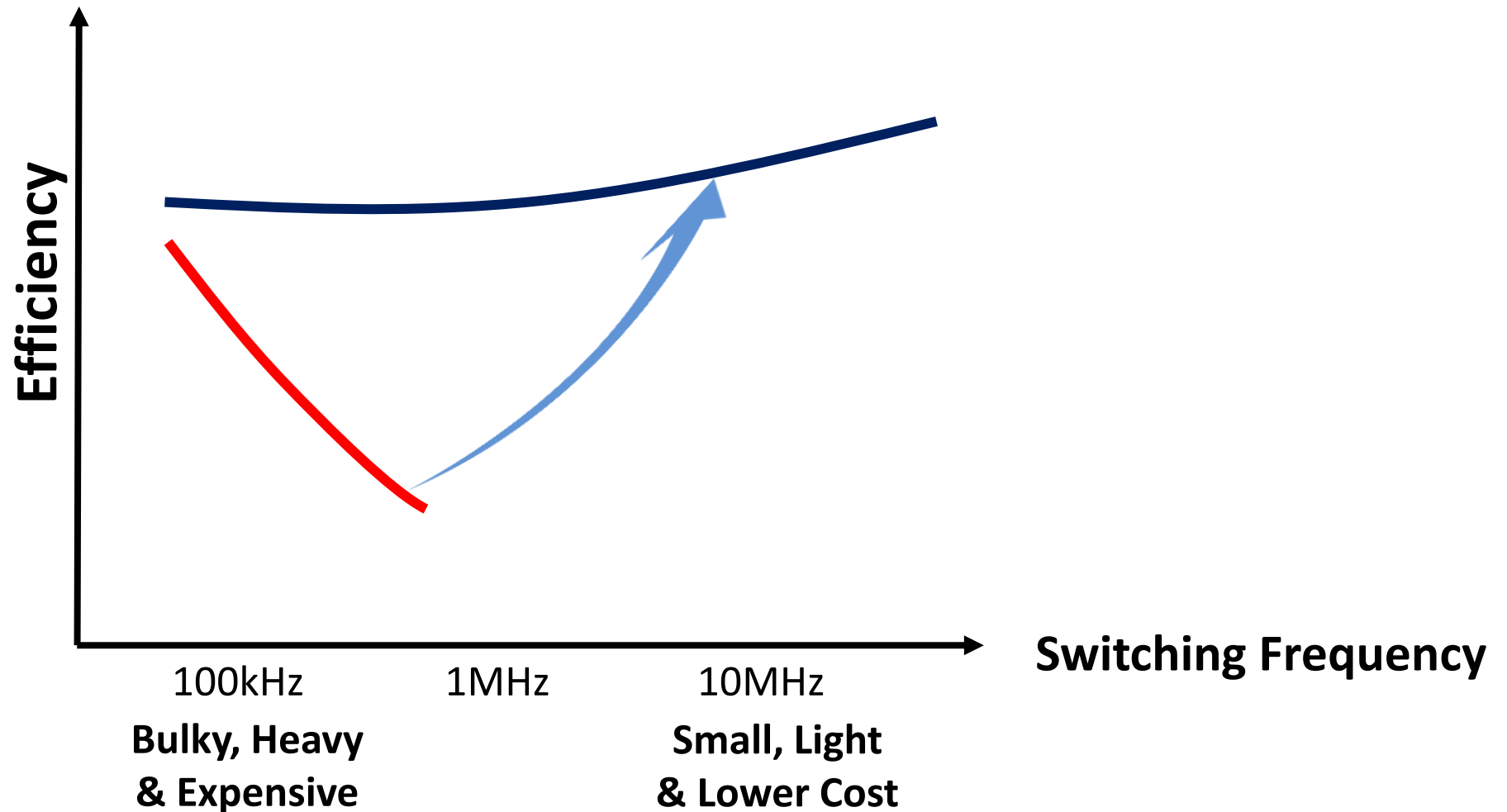
# The Si Landscape



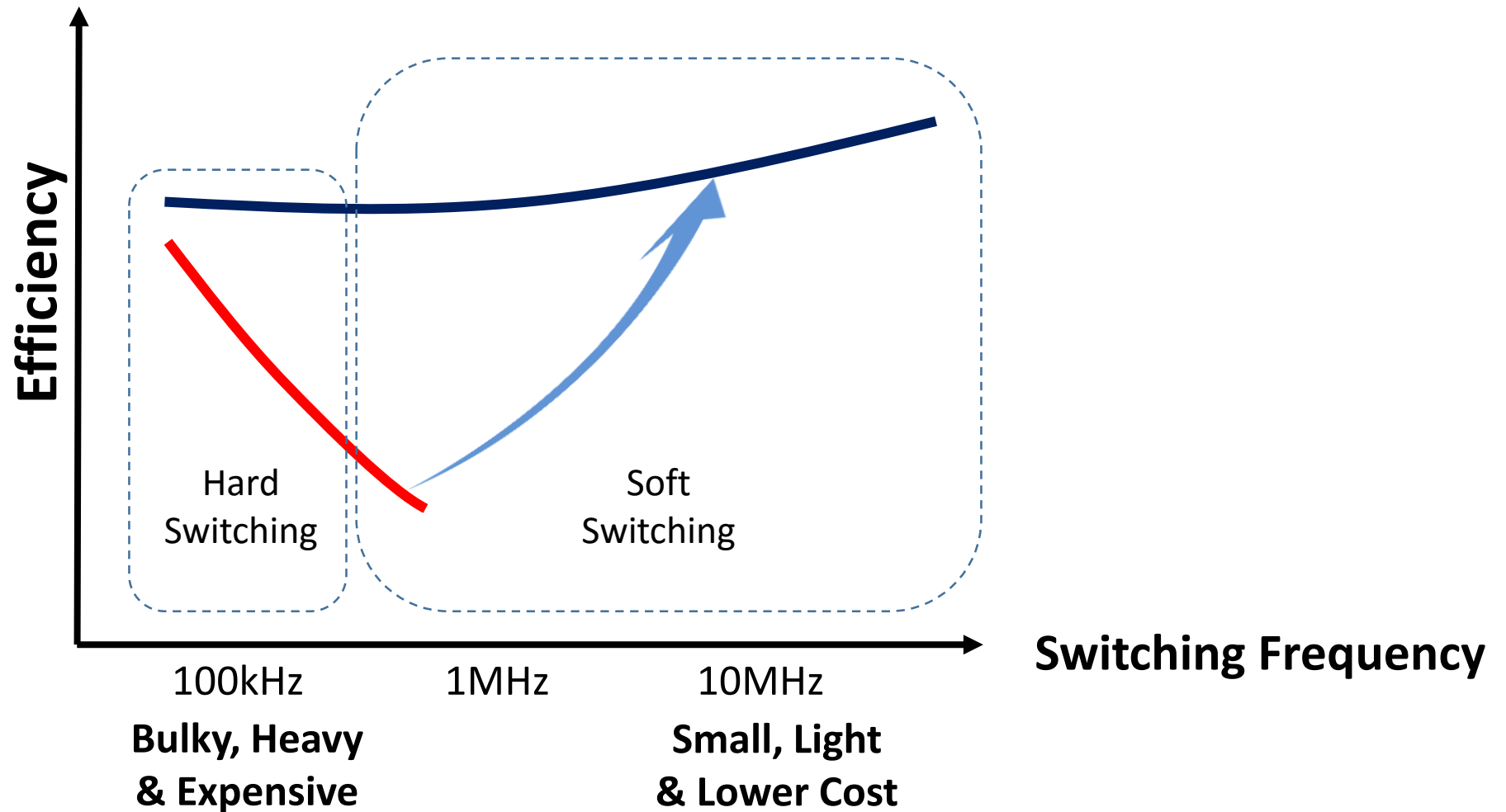
# The WBG Landscape



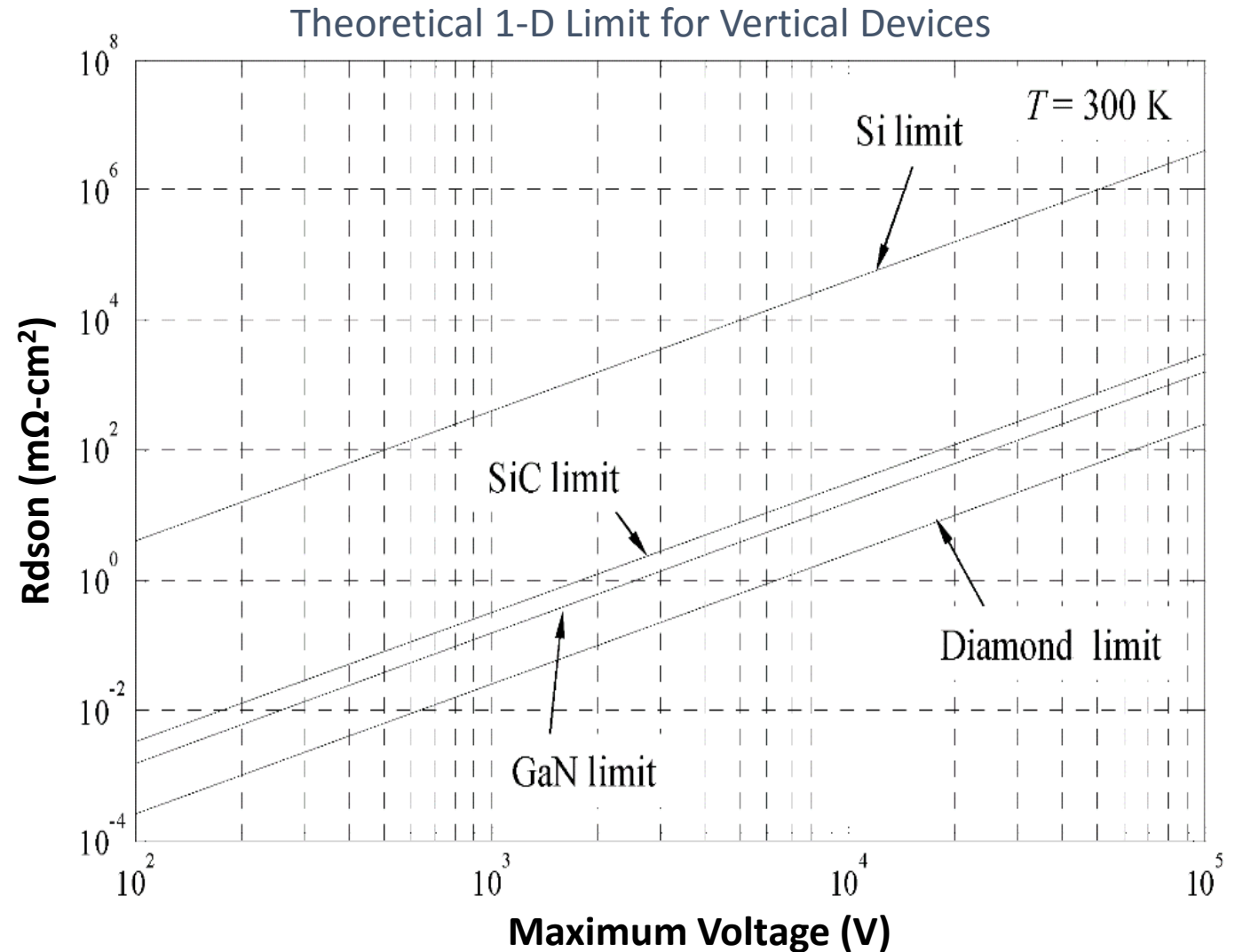
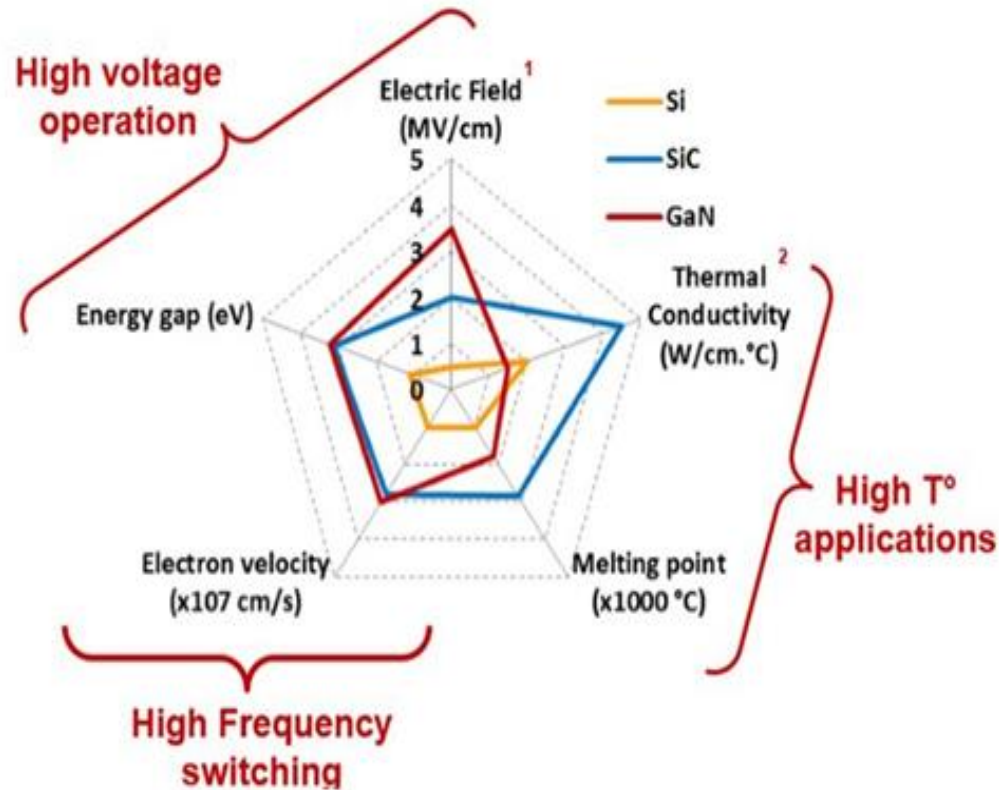
# Driving to Higher Speeds



# Driving Styles

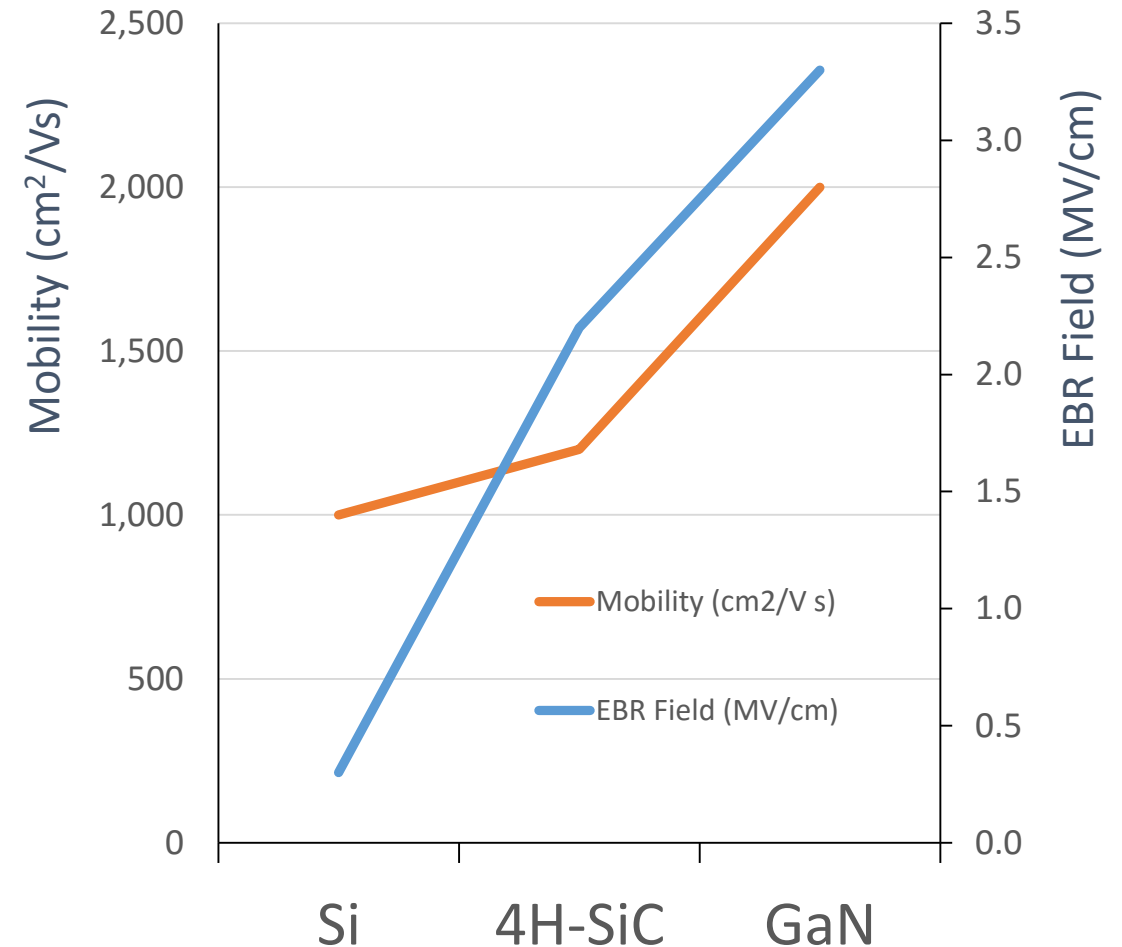
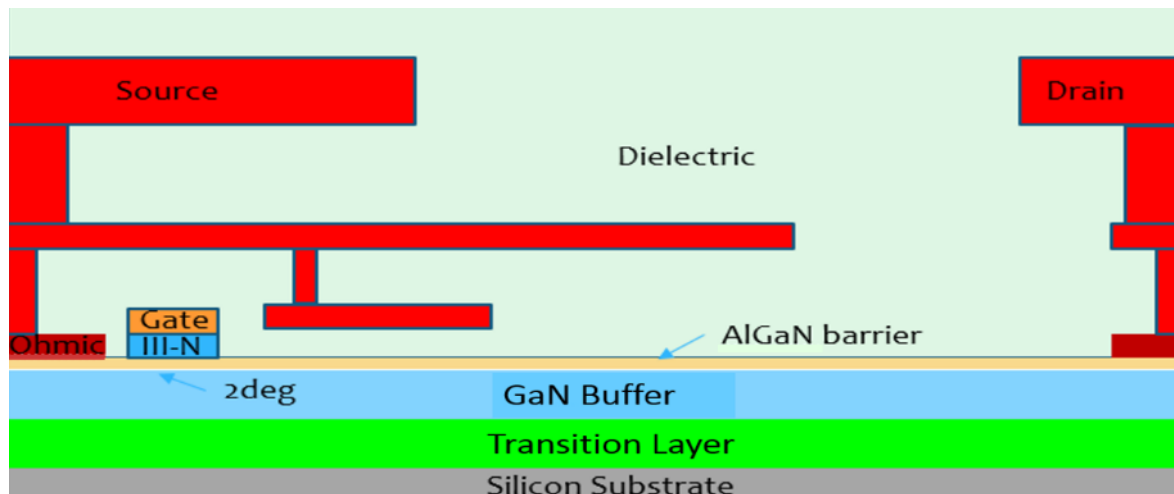


# Performance Limits of WBG Vertical Devices

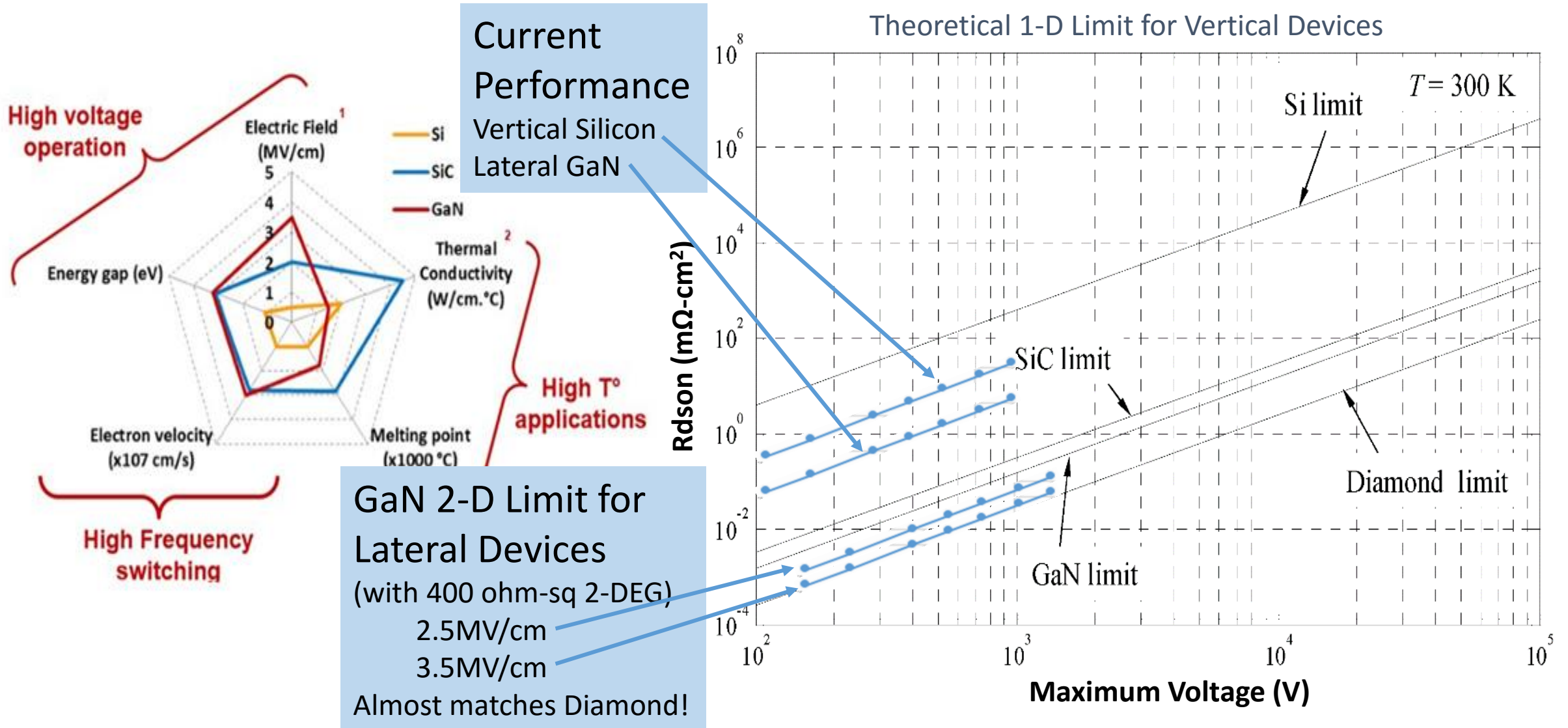


# Lateral GaN Advantage for Off-line Applications

- WBG GaN material allows high electric fields so high carrier density can be achieved
- Two-dimensional electron gas with AlGaN/GaN heteroepitaxy structure gives very high mobility in the channel and drain drift region
- Lateral device structure achieves extremely low  $Q_g$  and  $Q_{OSS}$  and allows integration
- Integration on silicon substrates means mature low cost wafer fabrication is available



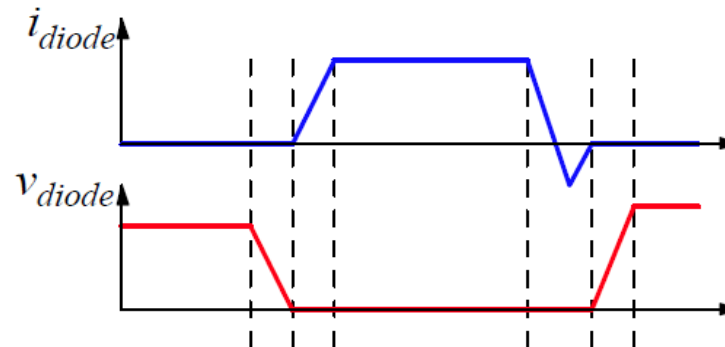
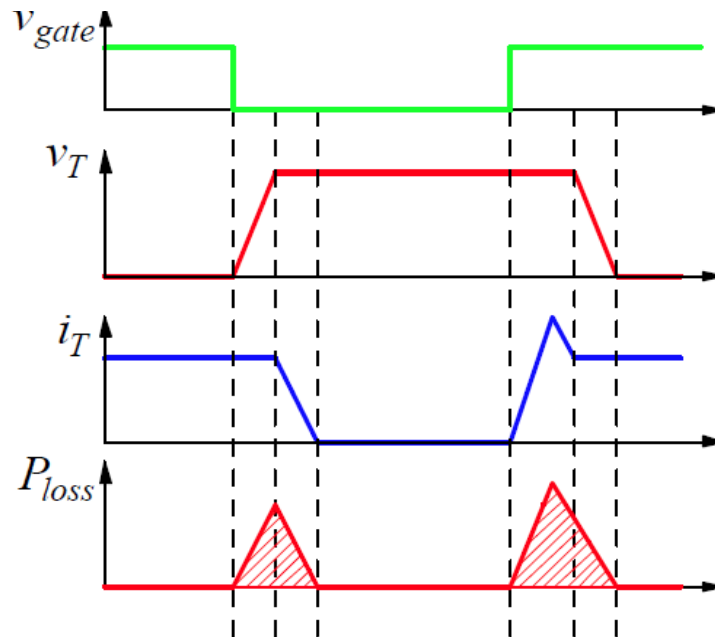
# Performance Limits of WBG Materials



# Hard-Switching

## Primary Switch Power Loss:

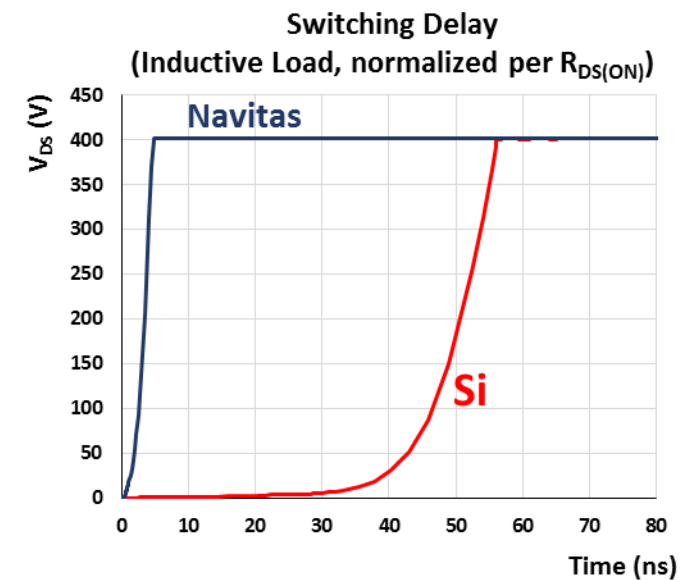
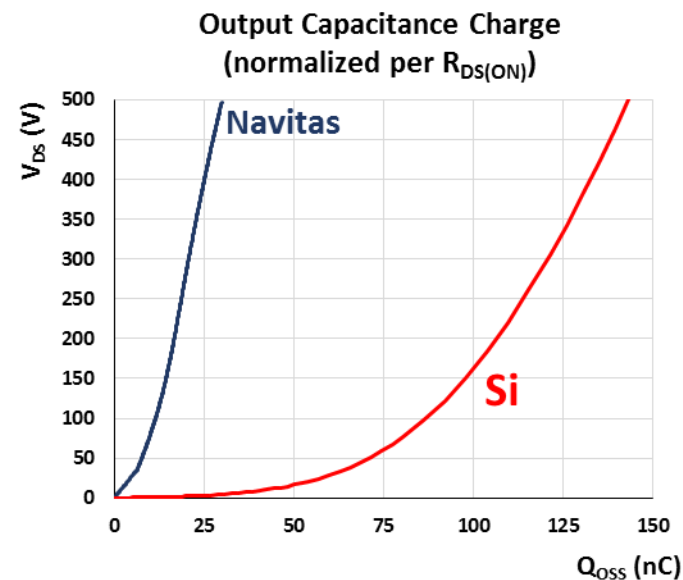
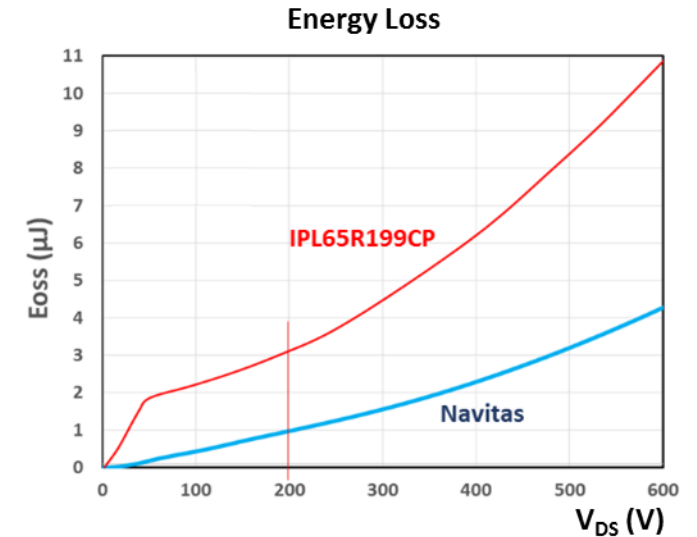
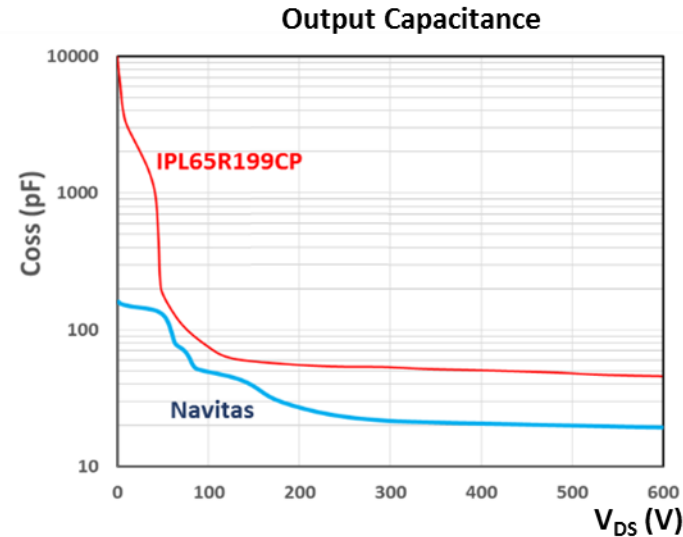
$$P_{FET} = P_{COND} + P_{DIODE} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$



$$P_{sw} \propto f_s [t_{c(on)} + t_{c(off)}]$$

# Si: High $C_{OSS}$ = Long ZVS Transition = Trapped Energy

- Hard Switching loss:  
 $P_{LOSS} = E_{OSS} * F_{SW}$
- High  $C_{OSS} \rightarrow$  Delay (limits  $F_{SW}$ )
- Too slow  $\rightarrow$  partial ZVS  $\rightarrow$   $E_{OSS}$  loss
- Si Superjunction  $C_{OSS}$  is 50x-100x higher than GaN at  $V_{DS} < 30V$
- Si SJ  $E_{OSS}$  is 3x higher than GaN at 200V (partial ZVS)
- Si SJ also has a high effective series resistance (ESR) and a lossy, hysteretic output capacitance, so even soft switching won't save it at high frequency



# Soft Switching with Si

## Primary Switch Power Loss:

$$P_{FET} = P_{COND} * k + P_{DIODE} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$

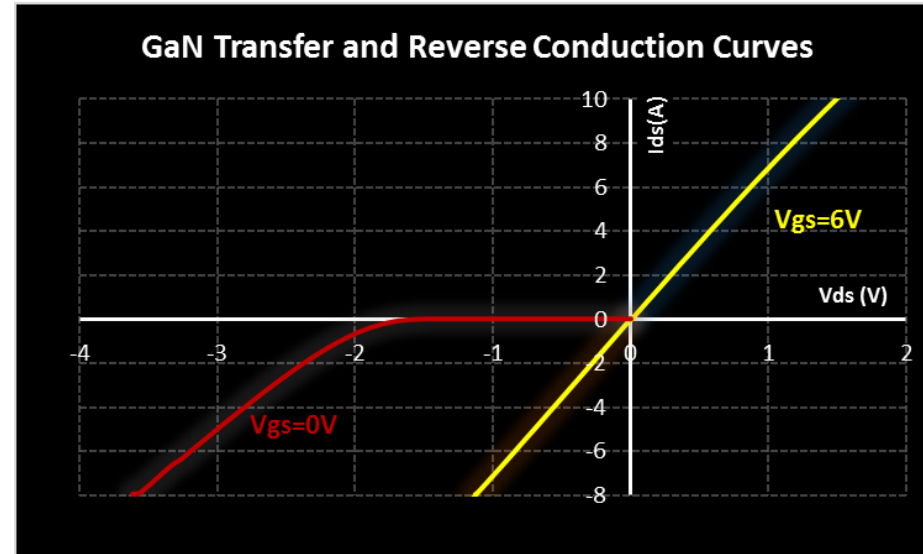
- k-factor      2 (or more) due to increased circulating current, duty cycle loss, high  $C_{OSS}$
- $P_{T-On}$       = 0 (soft, zero voltage switching)
- $P_{Qoss}$       ↓ 2-3X (most energy stored in output capacitance is recovered)

# ZVS LLC – Critical Parameters

	Si	Cascode GaN	eMode GaN
Partnumber	IPL60R199CP	TPH3206LD	Navitas
Voltage (V)	600	600	650
$R_{DS(ON)}$ (typ, mOhm)	180	150	160
$Q_G$ (typ, nC)	32	6.2	2.5
$C_{OSS(er)}$ (typ, pF)	69	64	30
$C_{OSS(tr)}$ (typ, pF)	180	105	50
$t_{rr}$ (typ, ns)	340	17	0
$Q_{rr}$ (typ, nC)	5,500	54	0
$R_{DS(ON)} \times C_{OSS(er)}$ (mOhm.pF)	12,420	9,600	4,800
$R_{DS(ON)} \times C_{OSS(er)}$ (mOhm.pF)	32,400	15,750	8,000

- Dead-time ( $t_d$ ) and magnetizing current ( $I_m$ ) discharge  $C_{OSS}$  to achieve ZVS\* ( $C_{OSS} \approx \frac{I_m t_d}{2V_{IN}}$ )
- eMode GaN has 2x-4x smaller  $C_{OSS}$ -related metrics than Si, cascode GaN
- Higher efficiency, higher frequency operation
- At 1MHz, GaN  $Q_G$  is so low, **gate drive loss ~zero**

# GaN $Q_G$ and Reverse Conduction



- Reverse Conduction

- LLC converters need low stored energy in output capacitance to sustain resonant transitions at light load
- Need low  $Q_{rr}$  and fast, robust body diode characteristics to avoid shoot-through current, peak drain-source voltage, and reverse recovery  $dv/dt^*$
- eMode GaN has no PN junction, so no minority carriers are injected and stored charge
- $Q_{rr}, t_{rr}, i_{rr} \sim \text{zero}$

# Soft-Switching with eMode GaN

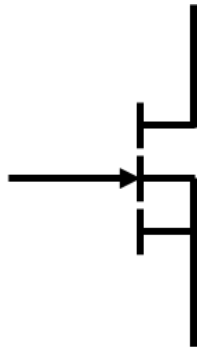
## Primary Switch Power Loss:

$$P_{FET} = P_{COND} \overset{\text{Minimized}}{* k} + \overset{\text{Reduced}}{P_{DIODE}} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$

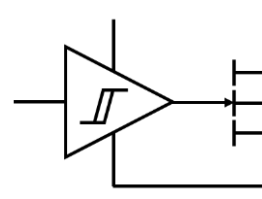
- k-factor >1 (less than Si) due to increased circulating current, duty cycle loss
- $P_{T-On}$  = 0 (soft-switch)
- $P_{Qoss}$  ↓ 10X ~~2-3X~~ (GaN  $C_{OSS}$  charging/discharging loss negligible up to 2MHz)
- $P_{DRIVER}$  ↓ 10X (GaN  $P_{DR}$  negligible up to 2MHz)
- $P_{QRR}$  = 0
- $P_{DIODE}$  ↓ 2X (reverse conduction loss reduced by synchronous rectification)
- $P_{T-OFF}$  = Reduced (limited by I-V crossover loss due to drive loop impedance)

# Creating the World's First AllGaN™ Power ICs

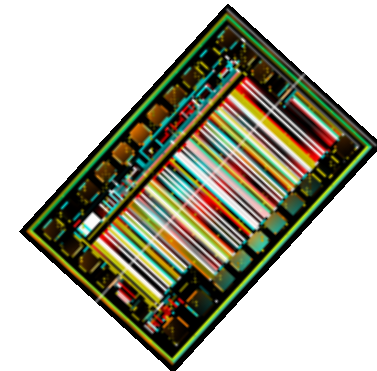
Fastest, most efficient  
GaN Power FETs



First & Fastest  
Integrated GaN Gate Driver



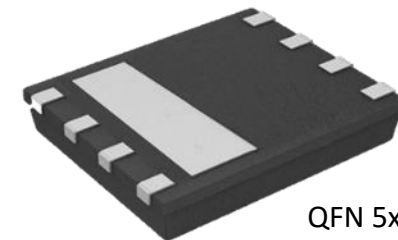
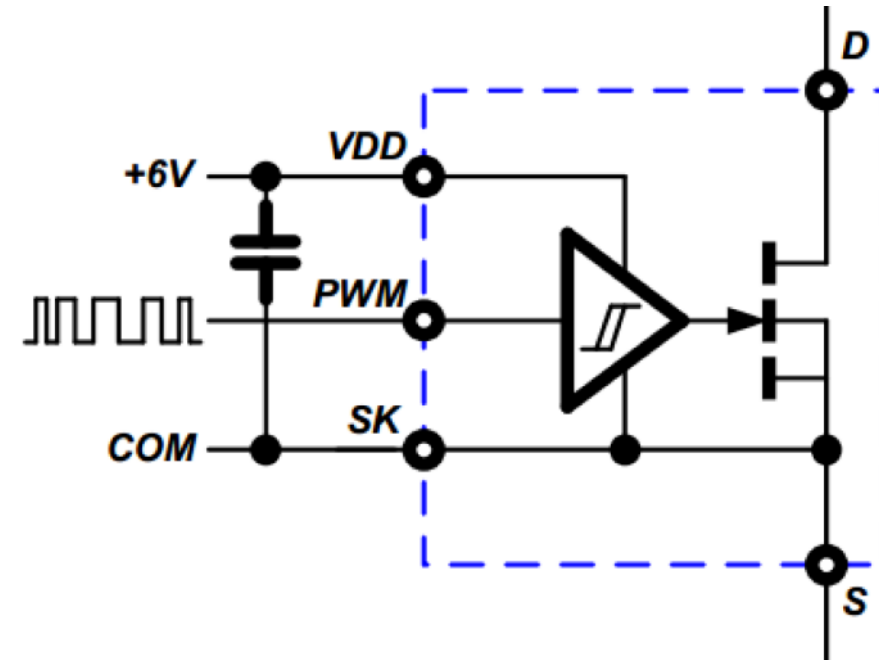
World's First  
AllGaN™ Power IC



Up to 40MHz switching, 4x higher density & 20% lower system cost

# GaN Power IC with Integrated Driver

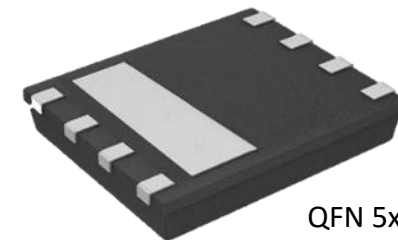
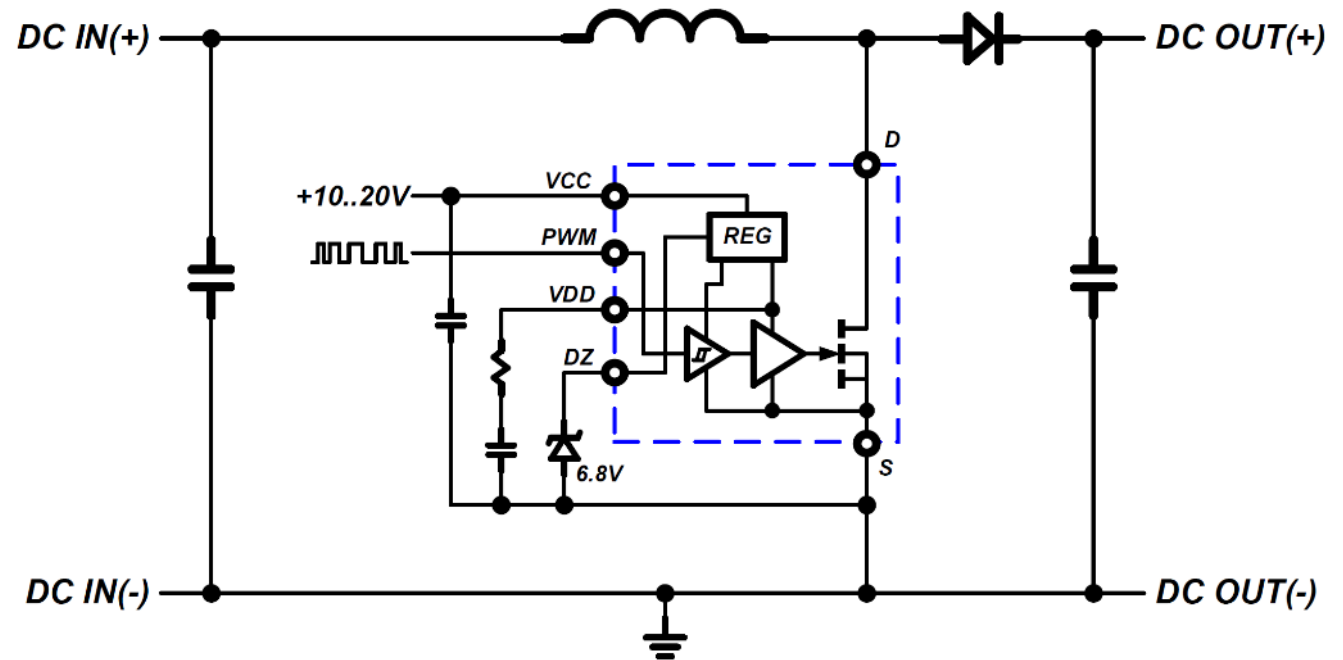
- Monolithic integration
- 20x lower drive loss than silicon
- Driver impedance matched to power device
- Shorter prop delay than silicon (10ns)
- Zero inductance turn-off loop
- High dV/dt immunity (200V/ns)
- Digital input (hysteretic)
- Rail-rail drive output
- Layout insensitive



QFN 5x6mm

# GaN Power IC – Next Step in Integration

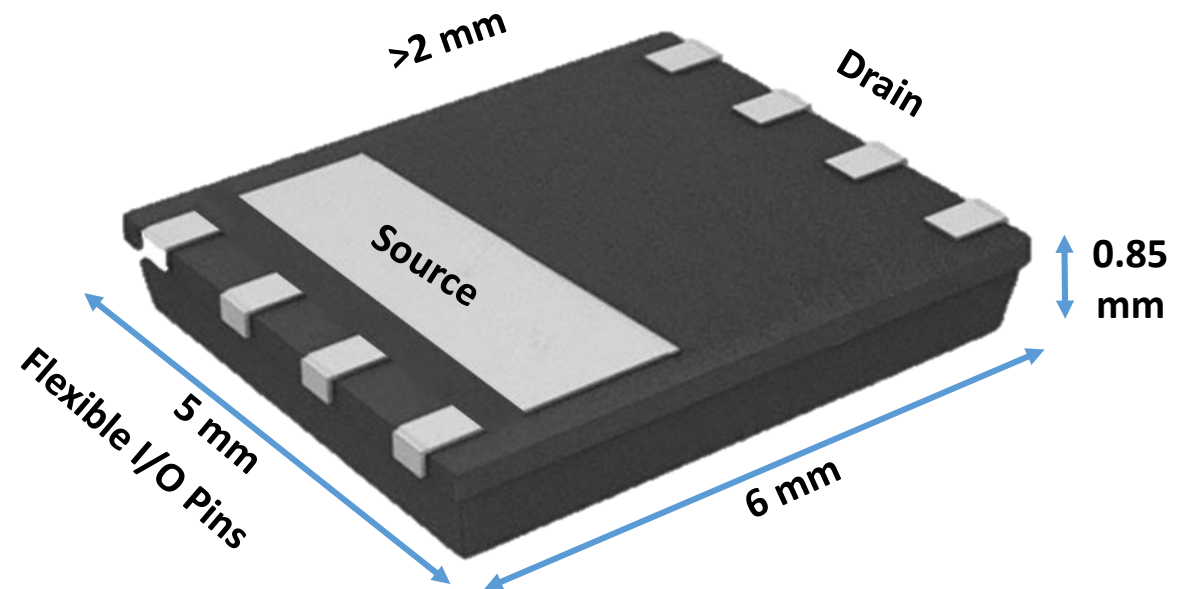
- Extended PWM input range
  - 3.3V, 5V, 15V, 20V input
- Wide  $V_{CC}$  range (10V-20V)
- On-board (monolithic) regulator
  - Zener-selectable gate drive voltage
  - Safe start up, power down
  - Internal UVLO
- Resistor programmable turn-on  $dv/dt$
- Standard QFN, simple layout



QFN 5x6mm

# Fast, Low Cost, Industry-Standard QFN

- Leadframe-based 5X6mm power package outline
- Low profile, small footprint with HV clearance
- Kelvin source connection for gate drive return
- Low inductance power connections ( $\sim 0.2\text{nH}$ )
- Low thermal resistance ( $< 2^\circ\text{C/W}$ )
- I/O pins enough for drive functions
- High volume
- Reliable
- Low cost



# Soft-Switching with GaN Power IC

## Primary Switch Power Loss:

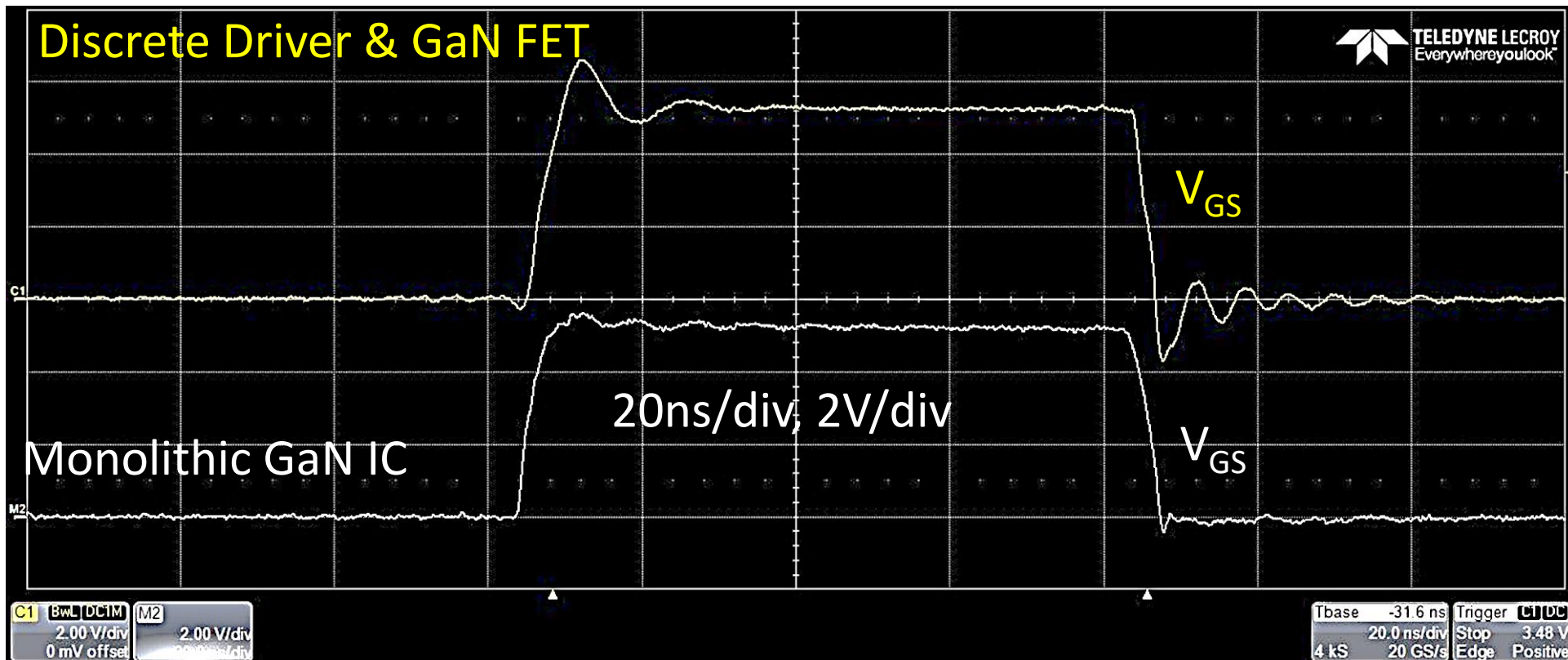
$$P_{FET} = P_{COND} \overset{\text{Minimized}}{\circledast} \overset{\text{Minimized}}{\circledast} k + P_{DIODE} + P_{T-ON} + P_{T-OFF} + P_{DR} + P_{QRR} + P_{QOSS}$$

- k-factor >1 due to increased circulating current, duty cycle loss
- $P_{T-On}$  = 0 (soft-switch)
- $P_{Qoss}$  ↓ 10X ~~2-3X~~ (GaN  $C_{OSS}$  charging/discharging loss negligible up to 2MHz)
- $P_{DRIVER}$  ↓ 10X (GaN  $P_{DR}$  negligible up to 2MHz)
- $P_{QRR}$  = 0
- $P_{DIODE}$  ↓ 3X ~~2X~~ (synchronous rectification with improved deadtime control)
- $P_{T-OFF}$  = 0 ~~Reduced~~ (near-zero drive loop impedance with integration)

**>10x frequency increase possible with higher efficiencies**

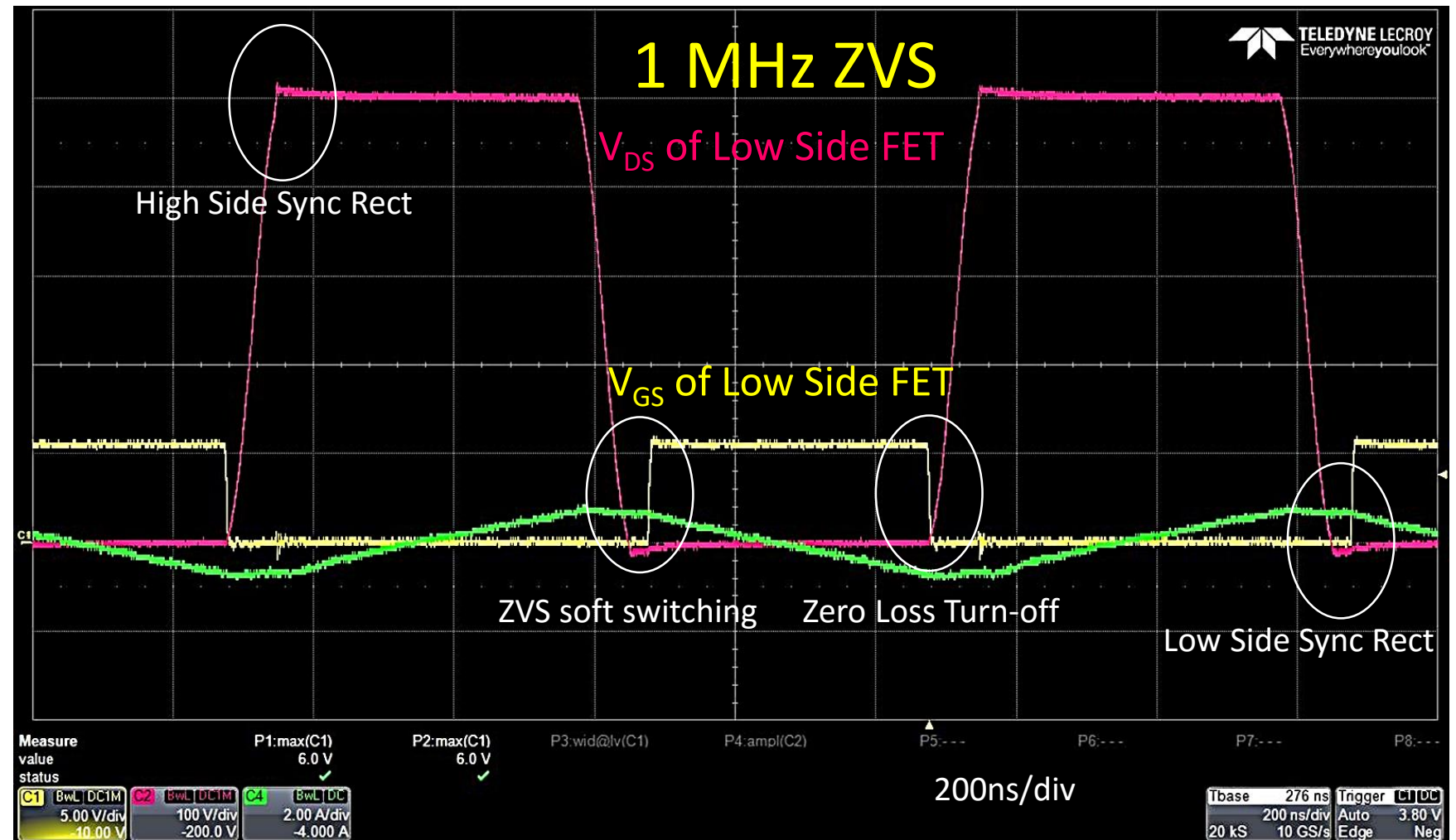
# Crisp & Efficient Gate Control

- Eliminates gate overshoot and undershoot
- Zero inductance on chip insures no turn-off loss



# GaN Power IC - Zero Loss Switching

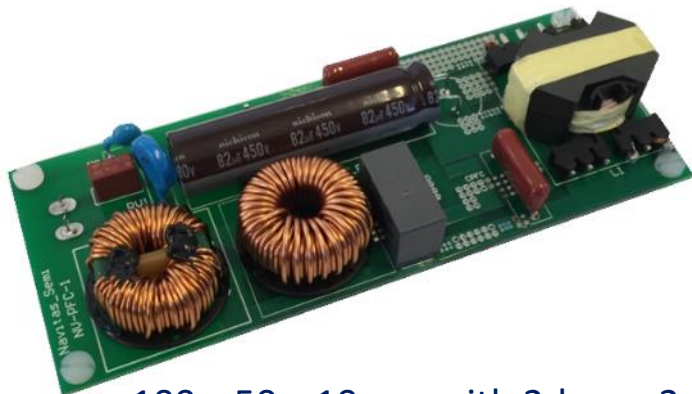
- 500V Switching
- No overshoot / spike
- No oscillations
- 'S-curve' transitions
- ZVS Turn-on
- Zero Loss Turn-off
- Sync Rectification
- High frequency
- Small, low cost filter



# GaN vs Silicon in 500kHz CrCM PFC

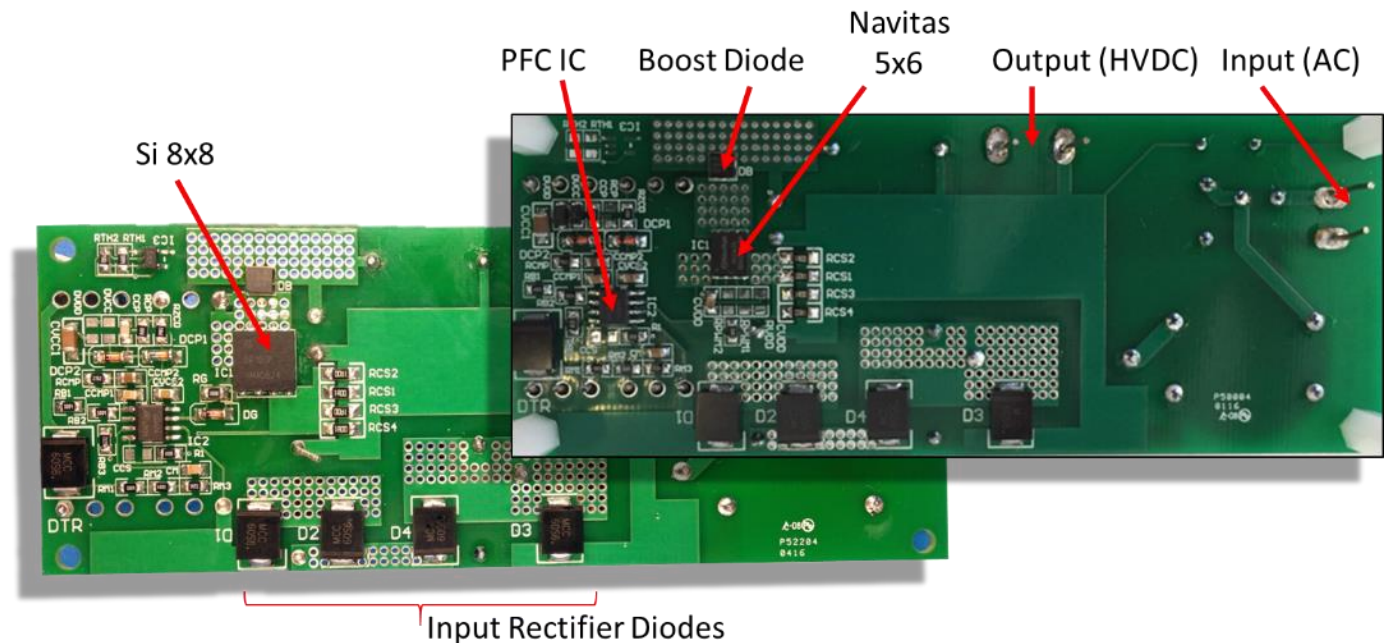
- Critical Conduction Mode (CrCM)
- $120V_{AC} = 167\text{-}230\text{kHz}$
- $220V_{AC} = 230\text{-}500\text{kHz}$
- 265V peaks at 1MHz *PFC IC* (L6562)  $F_{sw} max$

	Pack	$R_{DS(ON)}$ mΩ	$Q_G$ nC	$C_{OSS(er)}$ pF	$C_{OSS(tr)}$ pF	$R*Q_G$ mΩ.nC	$R*C_{OSS(tr)}$ mΩ.pF	$R*C_{OSS(er)}$ mΩ.pF
Navitas	5x6	160	2.5	30	50	400	8,000	4,800
Si CP Series	8x8	180	32	69	180	5,760	32,400	12,400
Si C7 Series	8x8	115	35	53	579	4,025	66,600	6,100
<b>GaN Benefits</b>	<b>&gt;50%</b>	<b>n/a</b>	<b>&gt;10x</b>	<b>&gt;2x</b>	<b>&gt;10x</b>	<b>&gt;10x</b>	<b>&gt;7x</b>	<b>&gt;2.5x</b>

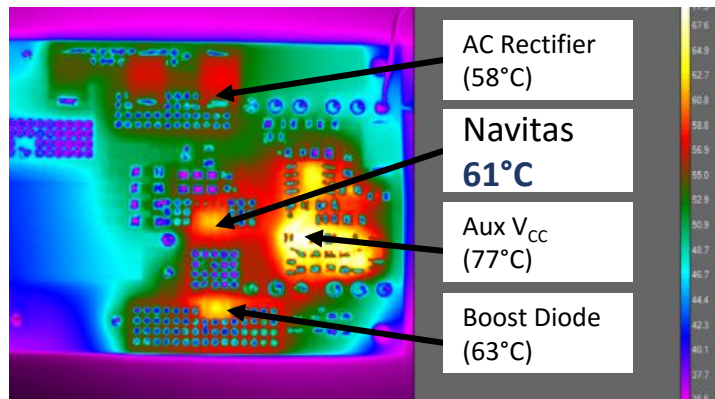


100 x 50 x 10mm with 2-layer, 2 oz Cu

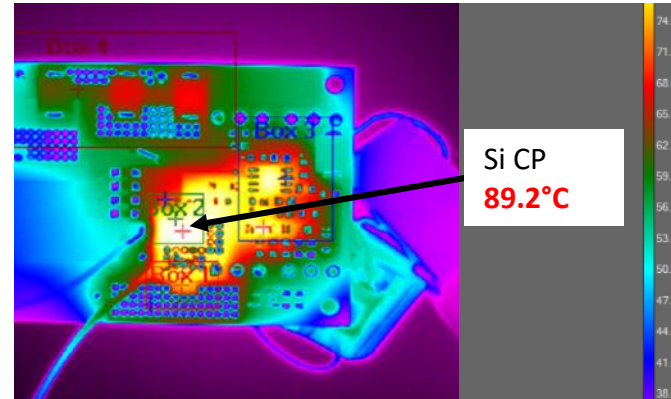
No heatsinks, no forced air,  
no glue, potting or heat spreaders



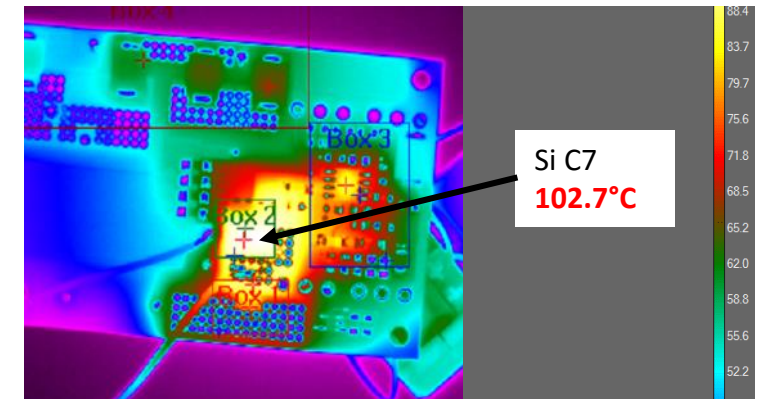
# Cool GaN, not Cool Silicon: High Line, Full Load



220V<sub>AC</sub>, 150W



220V<sub>AC</sub>, 150W

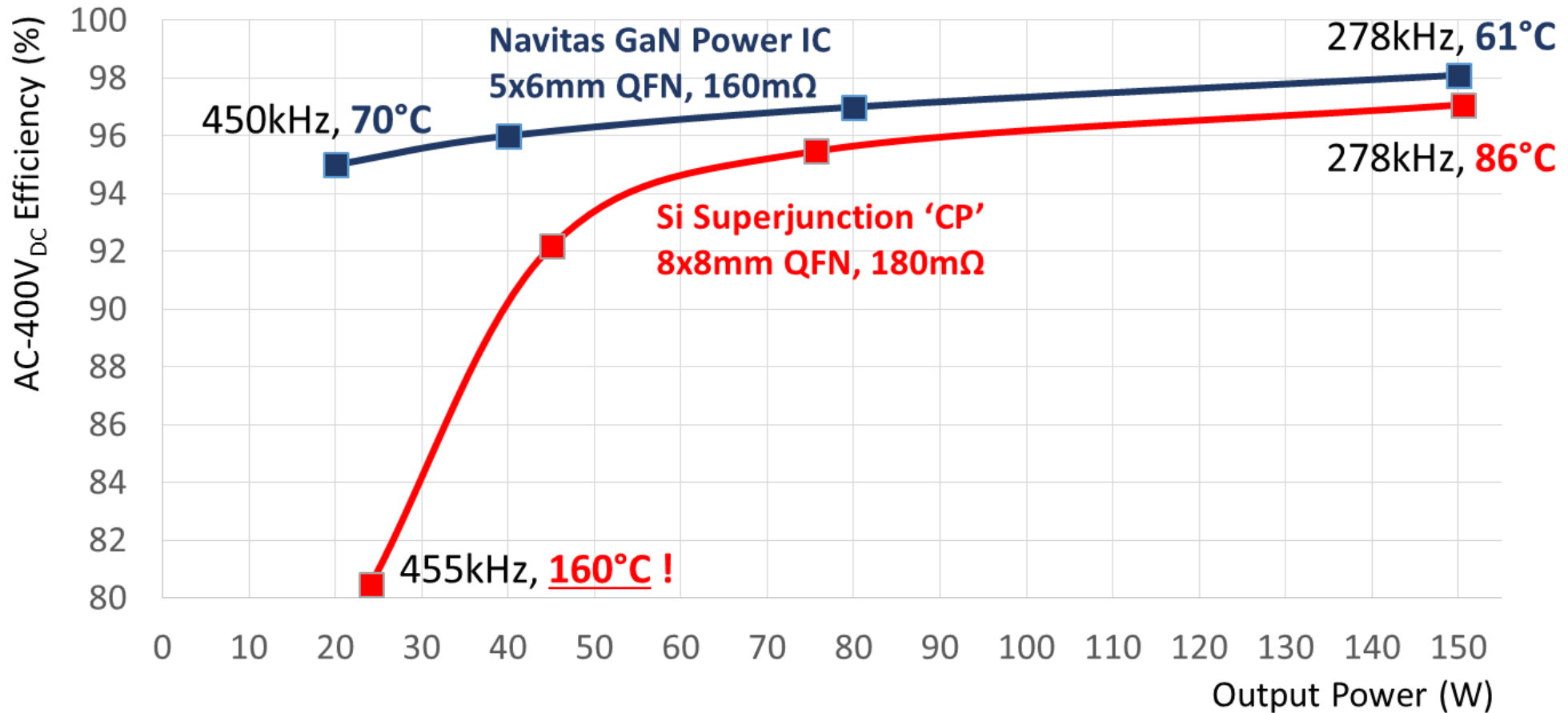


**180V<sub>AC</sub>**, 150W

- GaN runs cool (61°C)

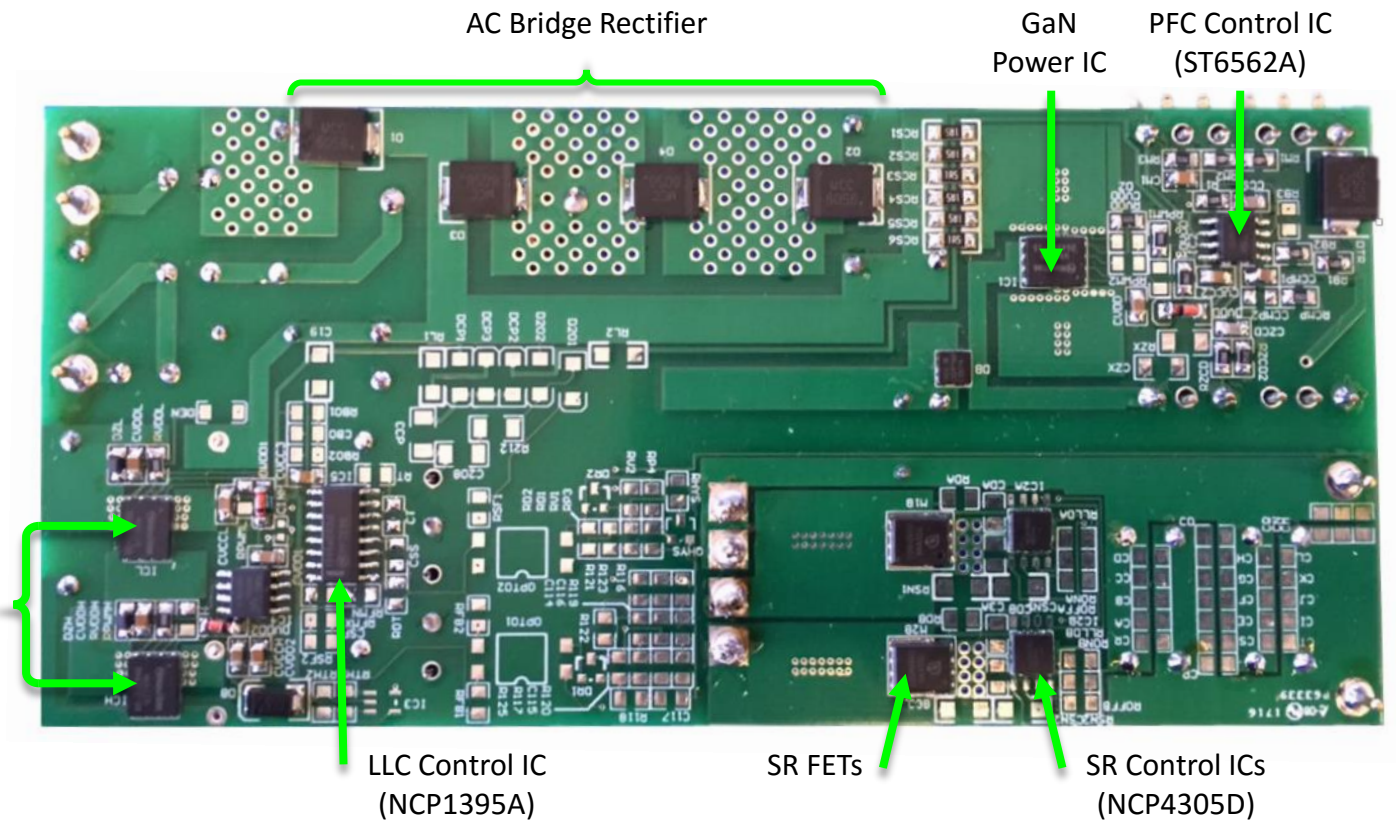
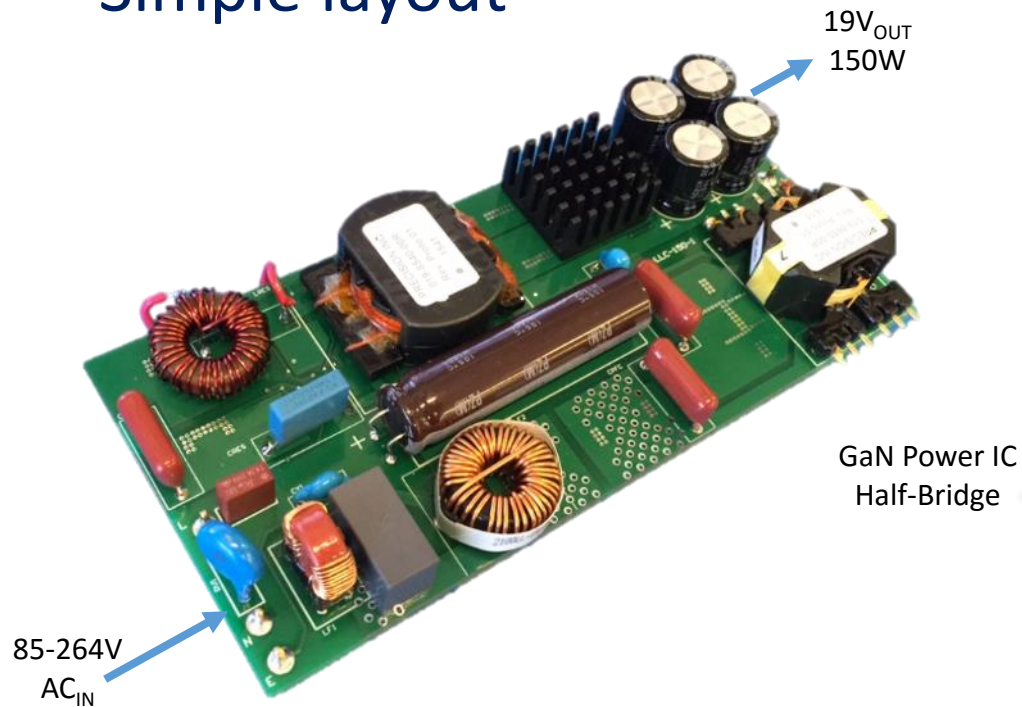
- CP Si running >90°C
- C7 Si too hot to run at 220V<sub>AC</sub>

# Cool GaN, not Cool Silicon: Driving Frequency



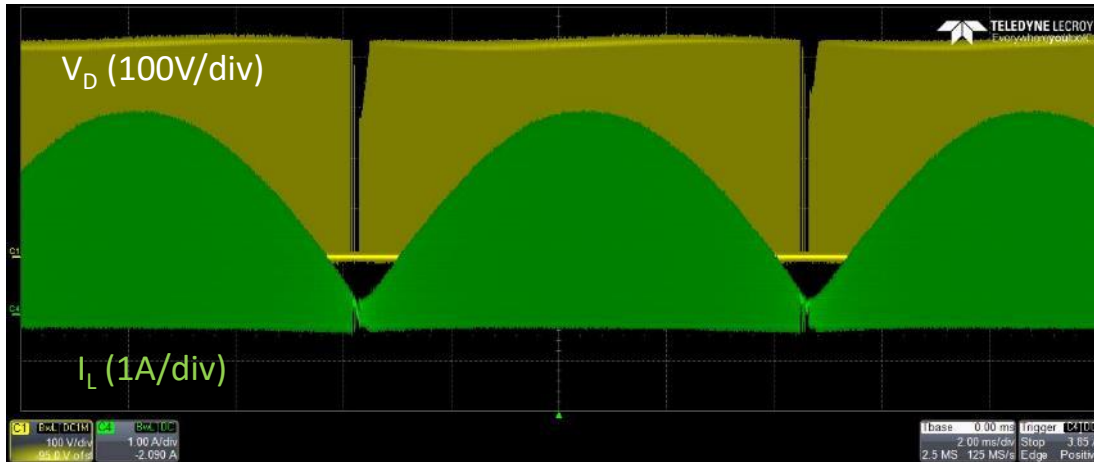
# AC-19V: GaN Power ICs in PFC, LLC

- Simple schematic
- Simple layout

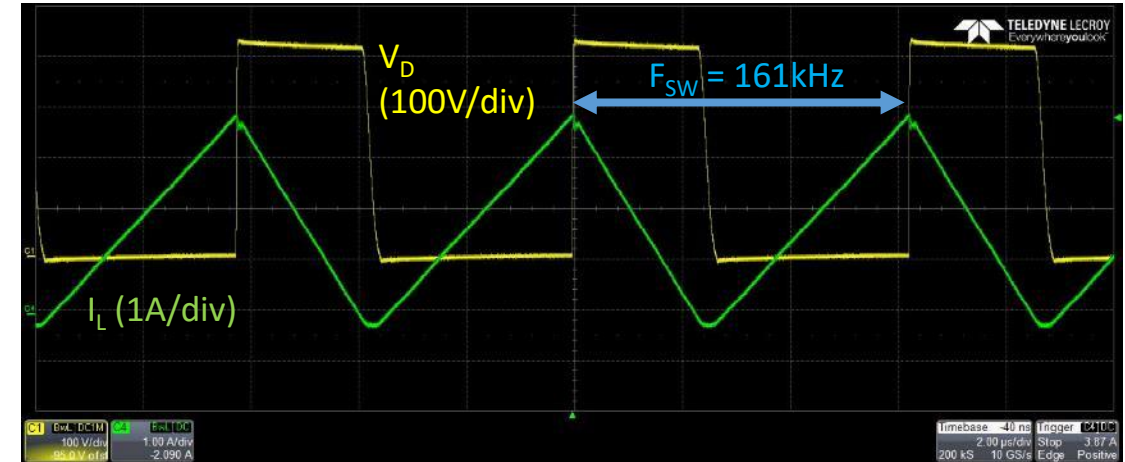


# CrCM PFC: High-Frequency, High Performance

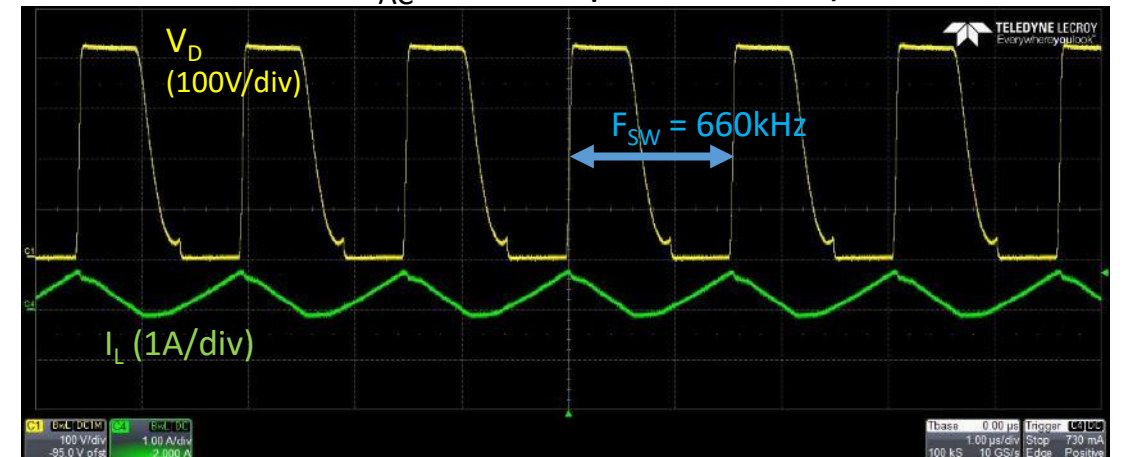
120V<sub>AC</sub>, 150W



120V<sub>AC</sub>, 150W, @peak AC line)

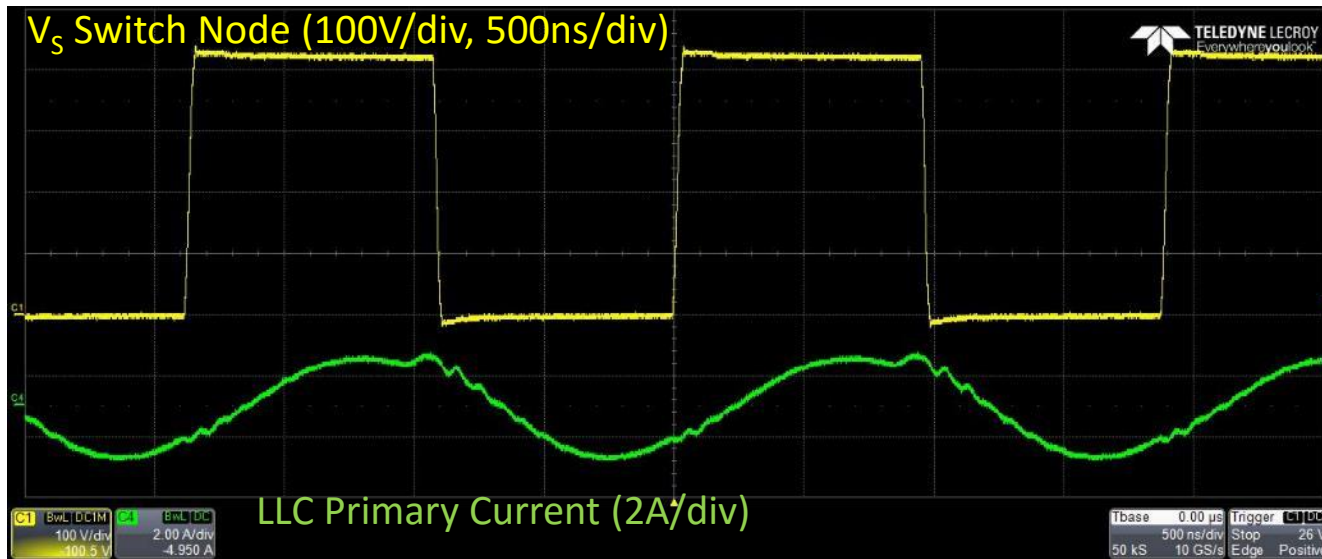


220V<sub>AC</sub>, 85W, @peak AC line)

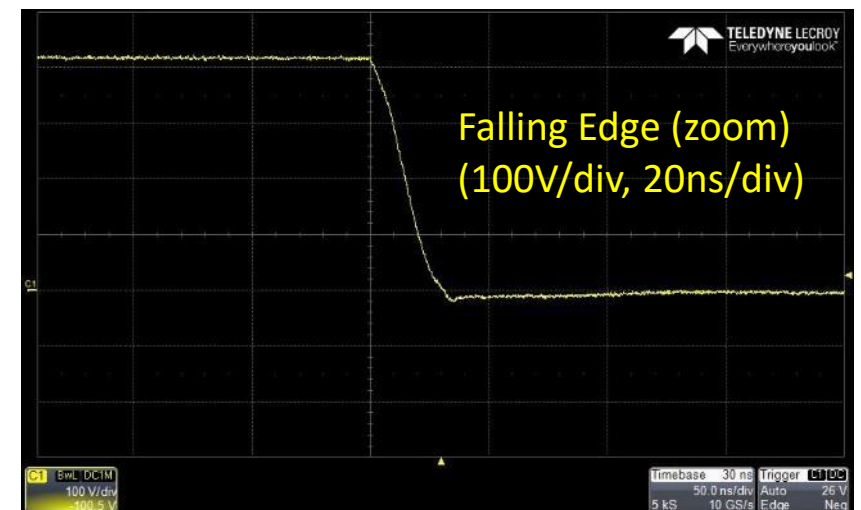
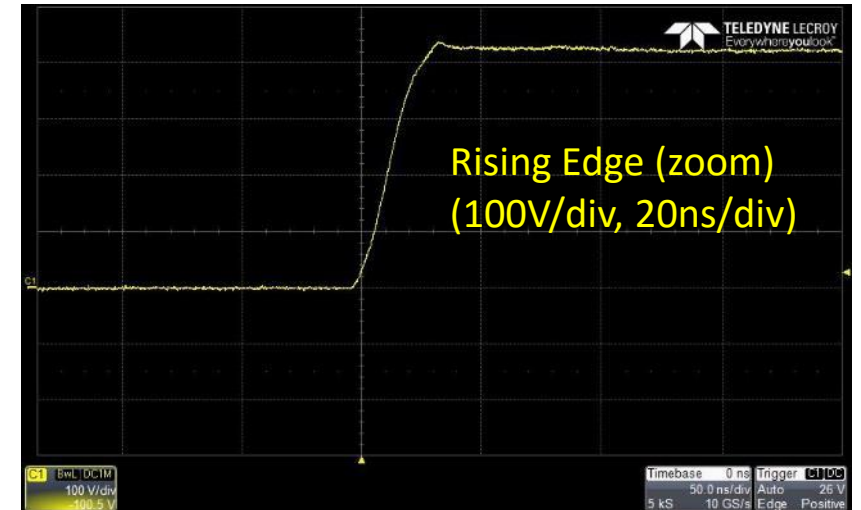


- Excellent Power Factor - PF >99.5%
- High frequency operation
- Easy to achieve ZVS soft-switching
- Negligible switching loss during partial ZVS at high line with GaN

# LLC: Smooth, Fast, Quiet

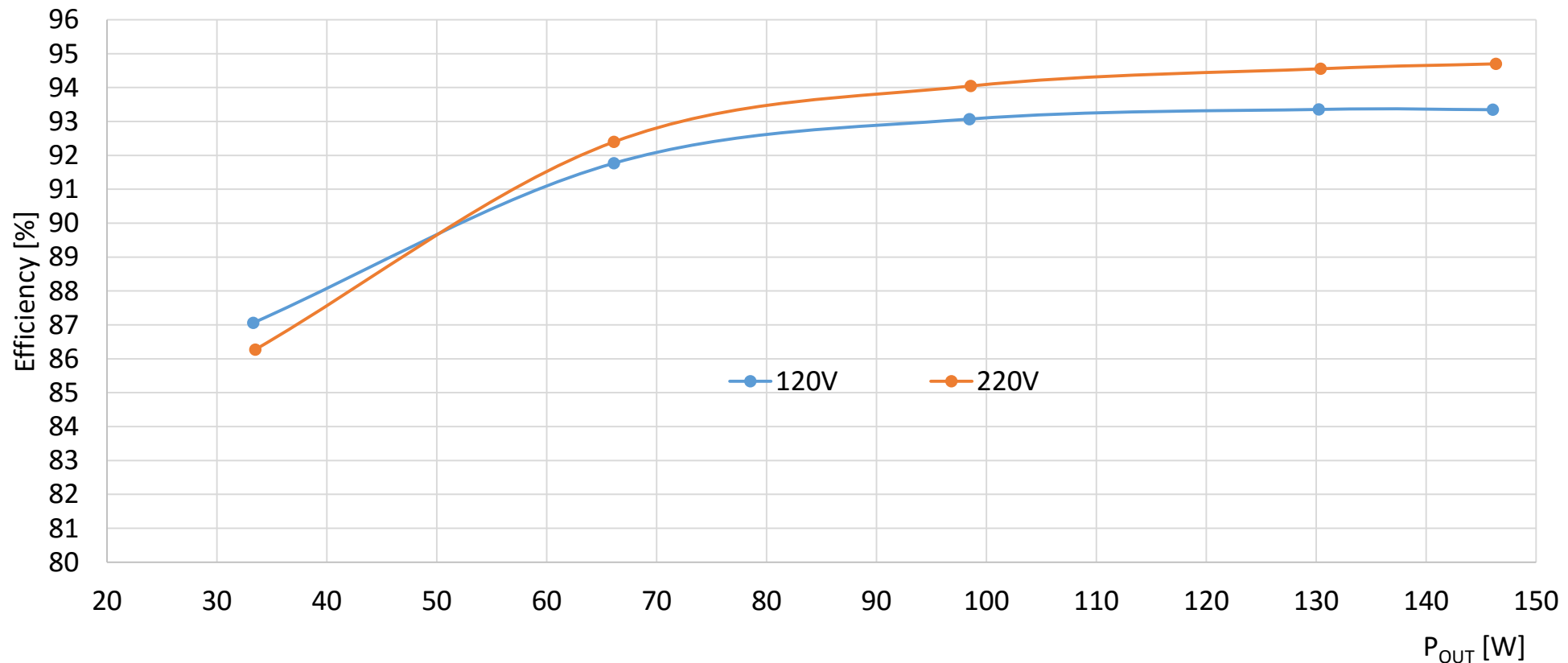


- No spikes, overshoot
- Smooth ‘S-curves’ with fast  $\sim 40\text{V/ns}$  slope
- Low EMI signature

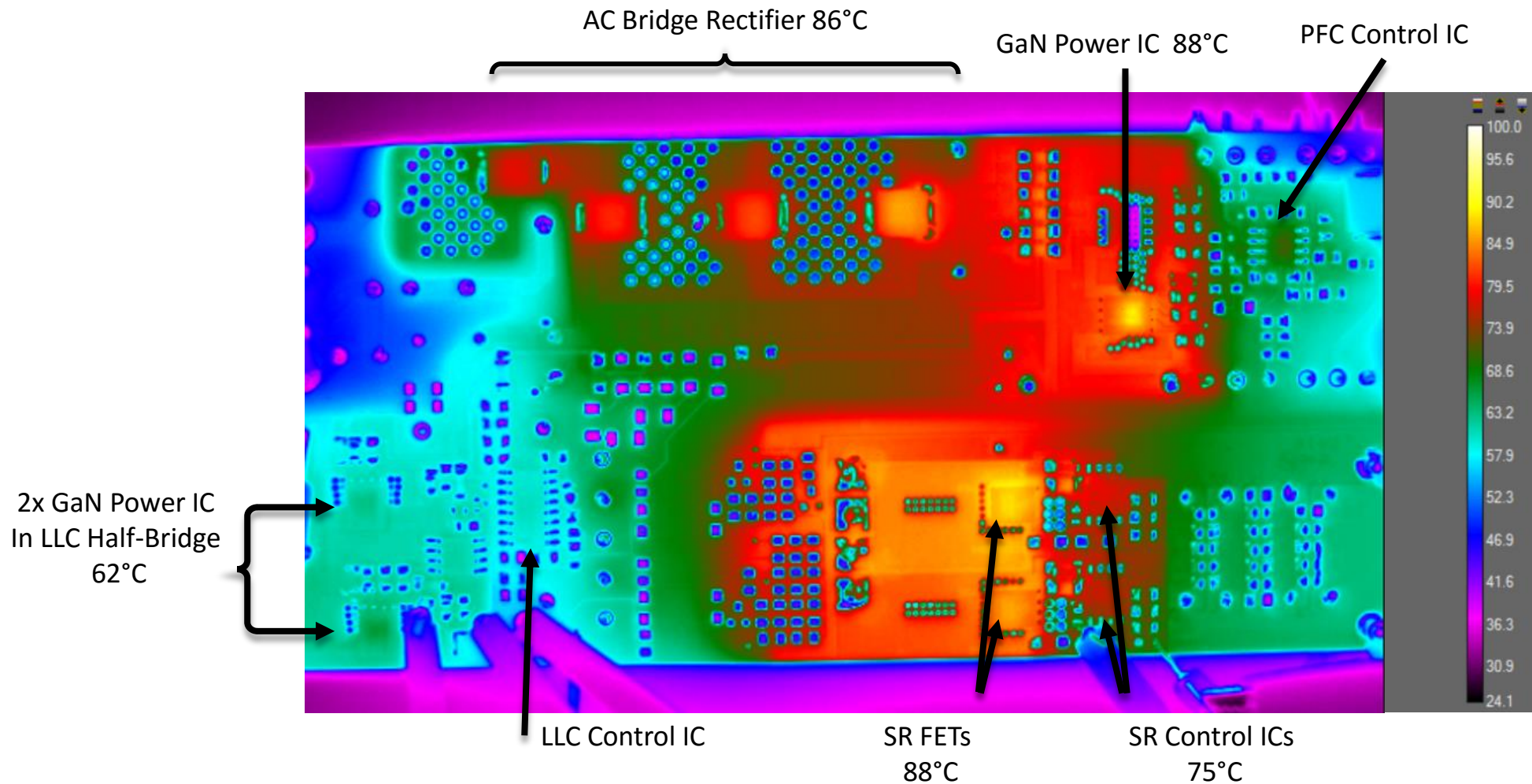


# High Efficiency at High Frequency

- AC-19V, 150W, 25°C, no airflow
- $120V_{AC} = 93.3\%$ ,  $220V_{AC} = 94.7\%$



# 150W, 90V<sub>AC</sub>, 500kHz (no airflow, 25°C)



# The MHz Eco-System

-  Navitas GaN Power ICs plus...

- High-frequency controllers (PFC, PWM, DSP, LLC, SR)



- High-frequency magnetics

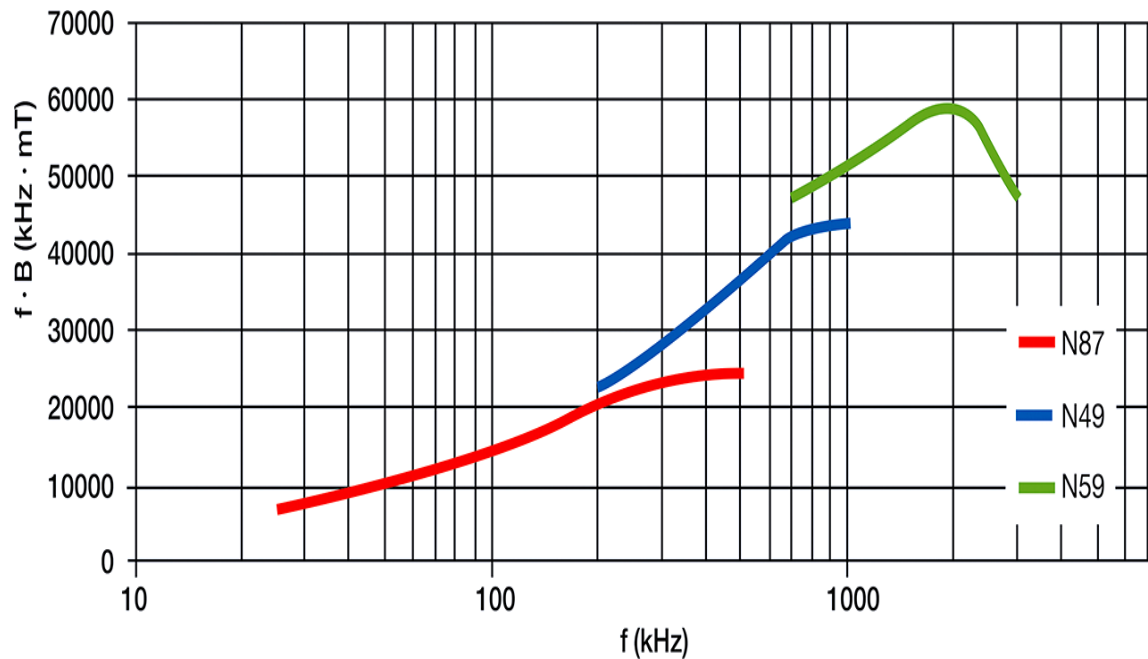


- High-frequency SR FETs

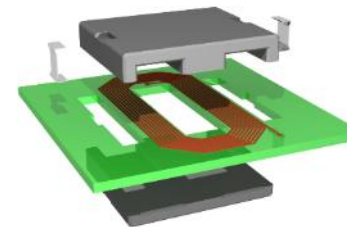
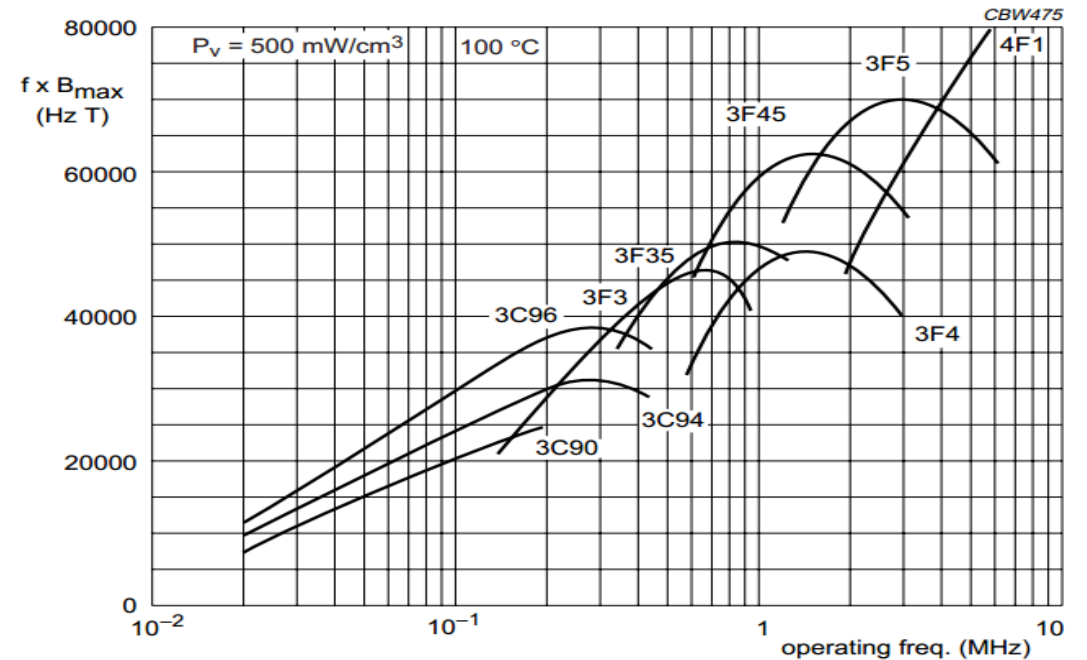


# High Frequency Magnetics 'GaN Optimized'

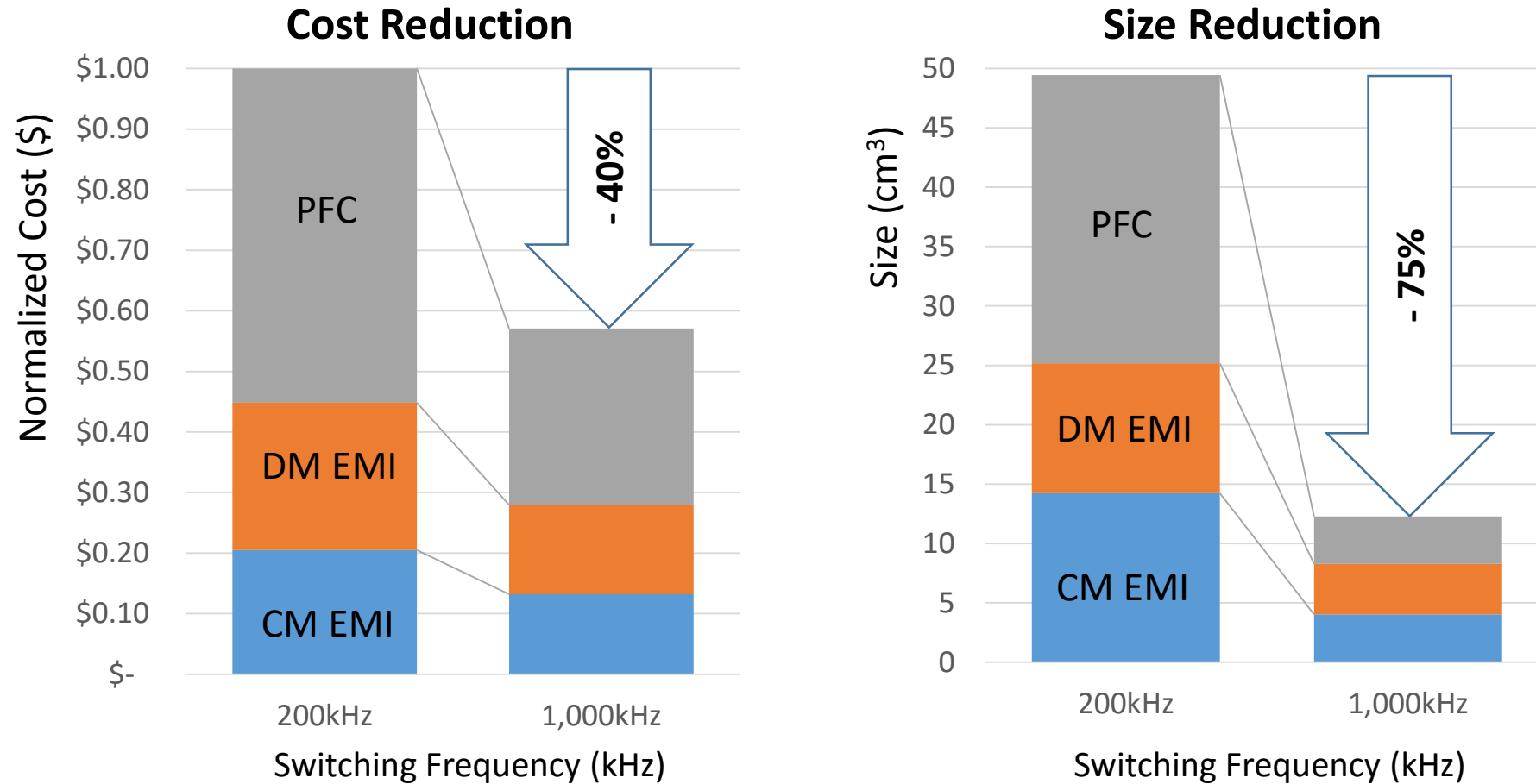
## N59 optimized for 2MHz



## 3F & 4F up to 10MHz



# Higher Frequency = Smaller, Cheaper



## Magnetics & EMI Filters

# Frequency drives 2x-4x Power Density

- Typical adapters (65-150kHz) = 5-12W/in<sup>3</sup>
- Navitas demo (500kHz) = 13.5W/in<sup>3</sup>
- Navitas customer estimate = 20-25W/in<sup>3</sup>



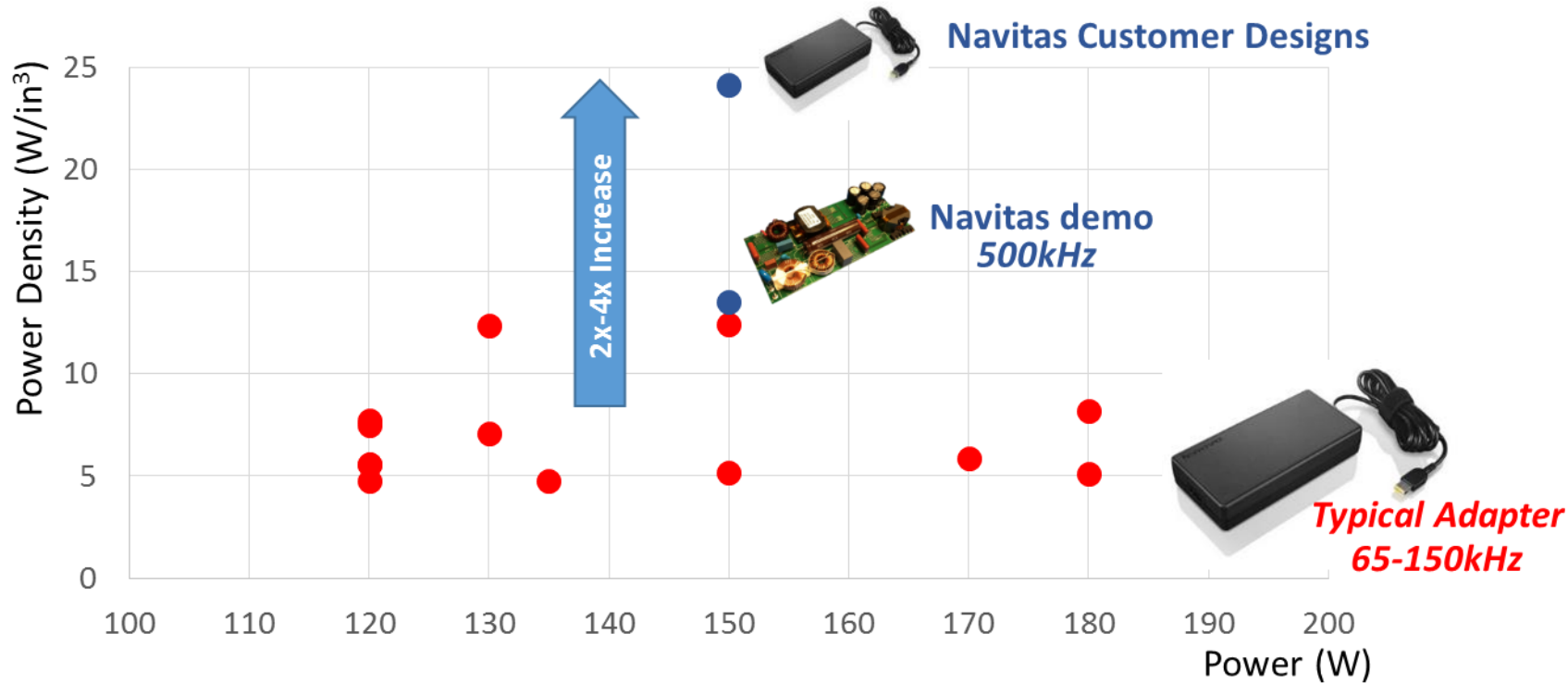
Gamer Laptops (100-150W)



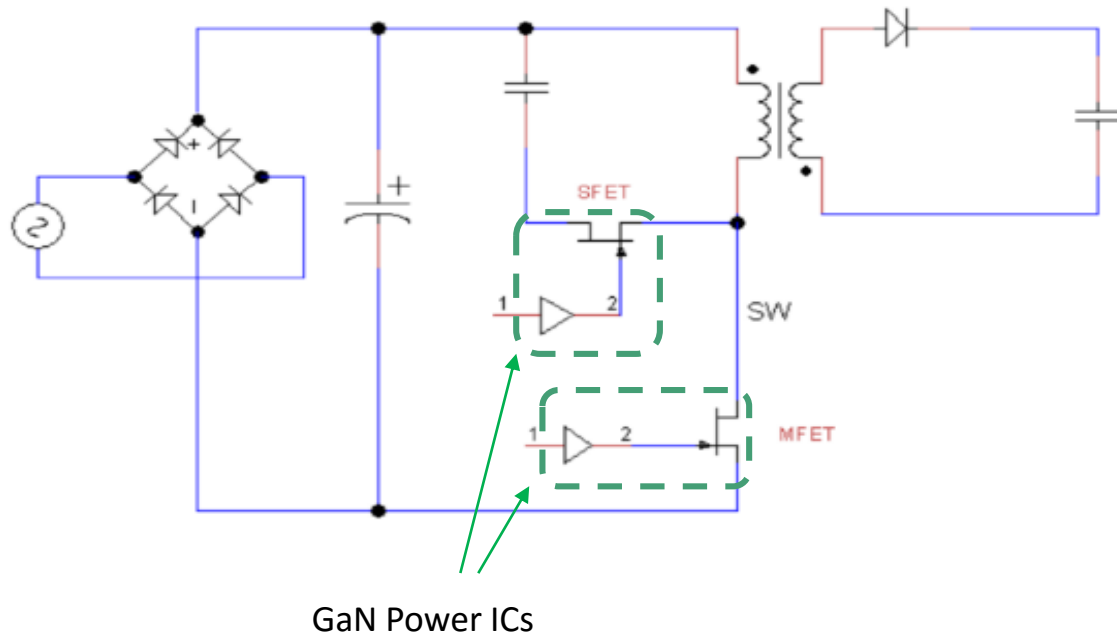
All-in-One PCs (150-200W)



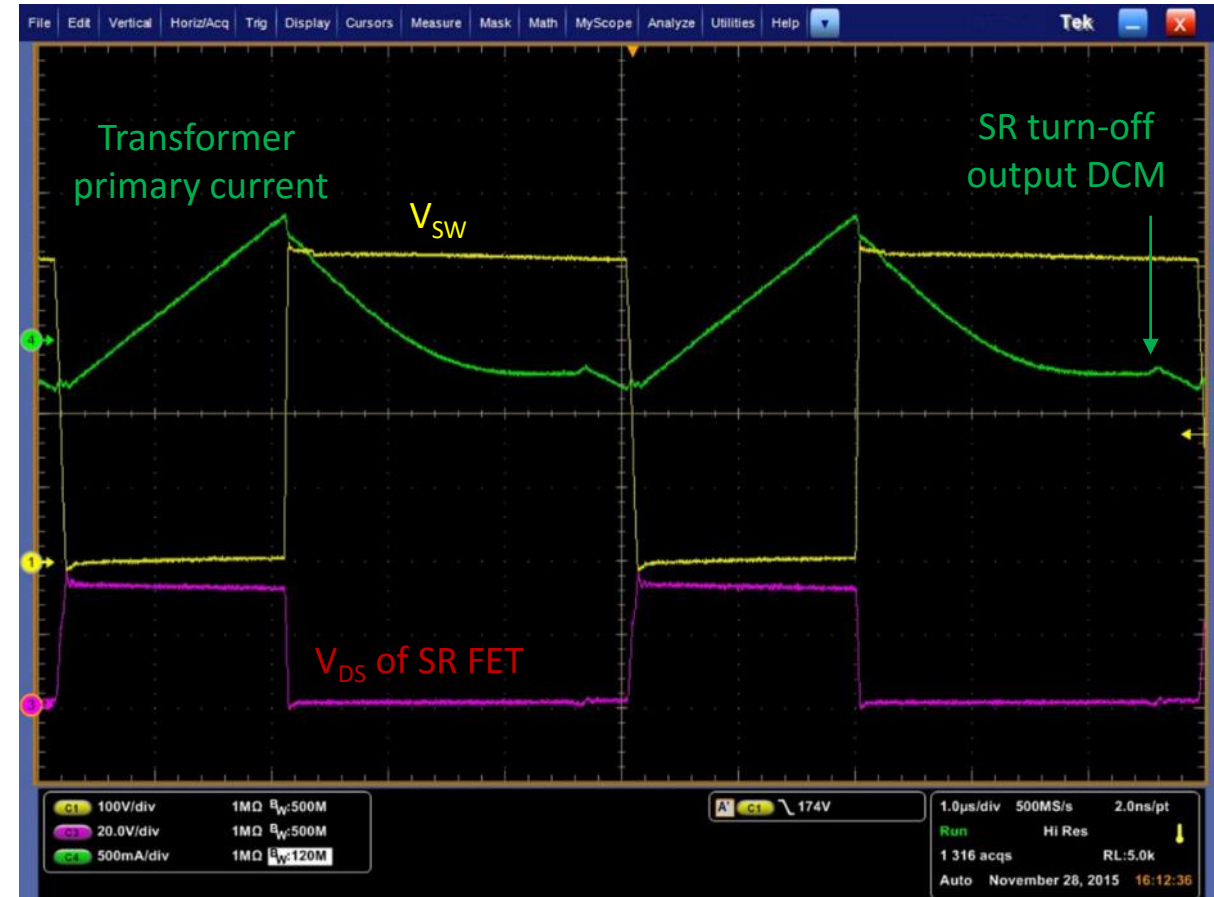
38"-52" TVs (100-200W)



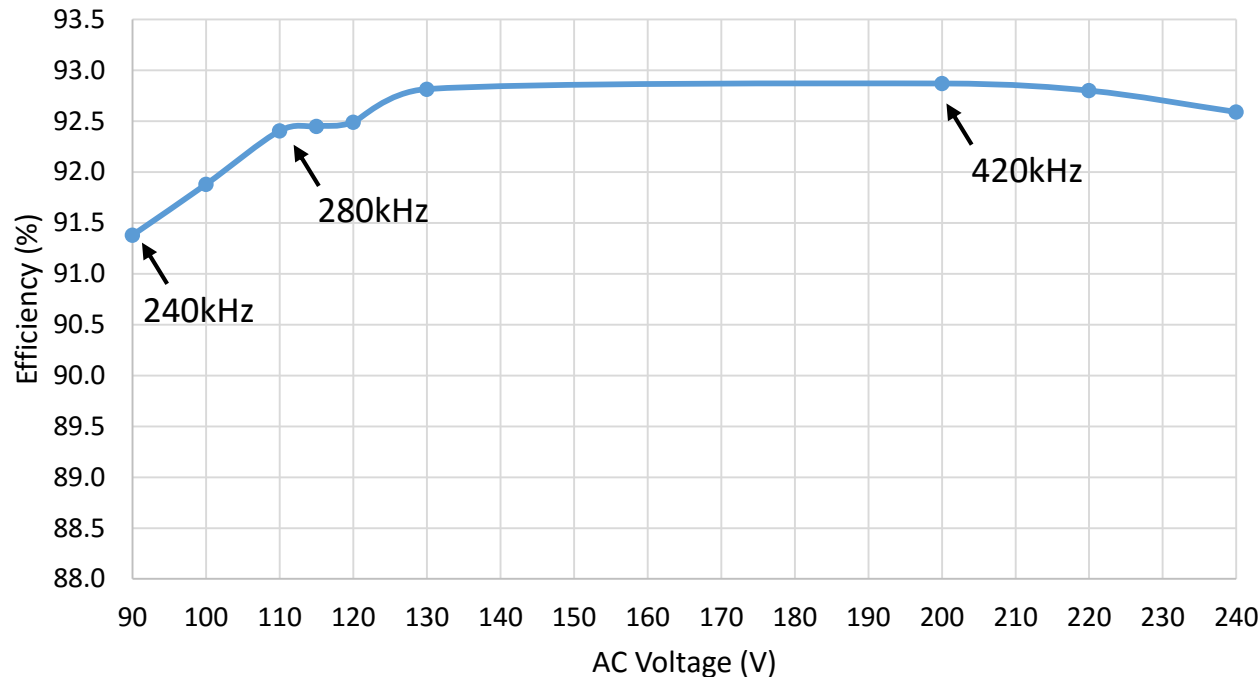
# Soft-Switching: Active Clamp Flyback (ACF)



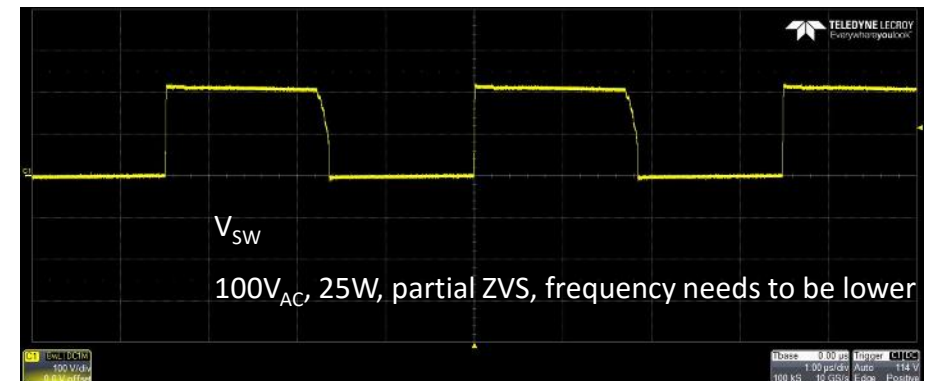
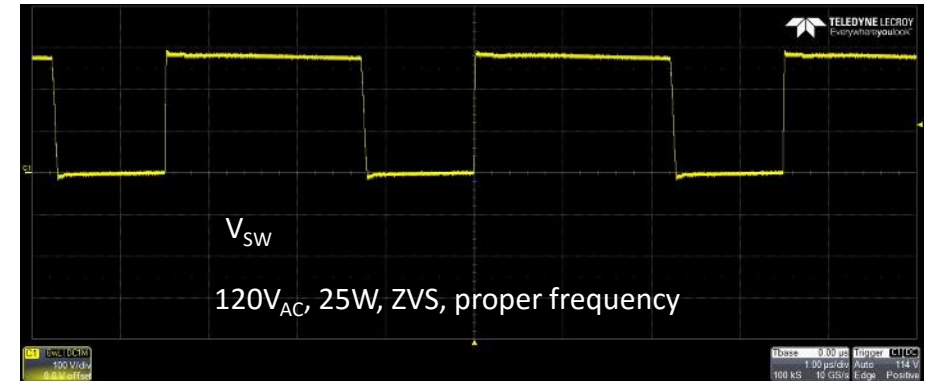
- ACF\* gives highest efficiency, highest power density for adapters 20W-75W
- No snubber loss
- Reduced voltage across primary FETs



# Navitas 25W ACF: Frequency, Efficiency



- Existing ACF control IC
  - Uses variable frequency control to maintain critical DCM
  - Too high frequency loses soft switching
  - Too low frequency generates excessive negative current
  - Limited frequency
- New, higher frequency ACF controllers – expect +0.5%



# Quiet EMI

- Conducted EMI (CISPR Class B)\*
- Quasi-peak, 120V<sub>AC</sub>, 285kHz
- Quiet performance
  - Controlled switching
  - No spikes, no overshoot
  - ‘S’-curve transitions
- Simple EMI filter design\*\*

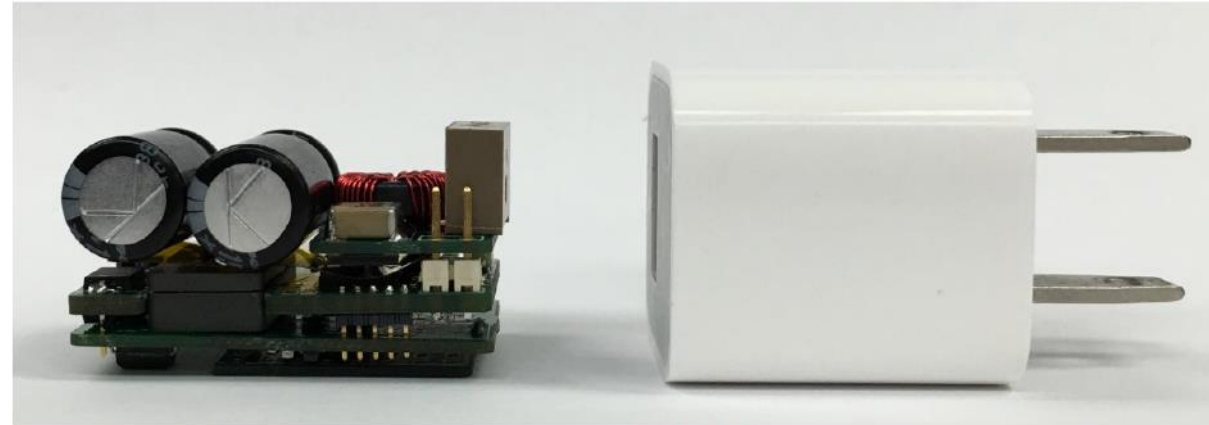


\*\*Refer also to: “Design Considerations of MHz Active Clamp Flyback Converter with GaN Devices for Low Power Adapter Application”, Huang, et al, VPT, APEC 2016

“Conducted EMI Analysis and Filter Design for MHz Active Clamp Flyback Front-End Converter”, Huang, et al, VPT, APEC 2016

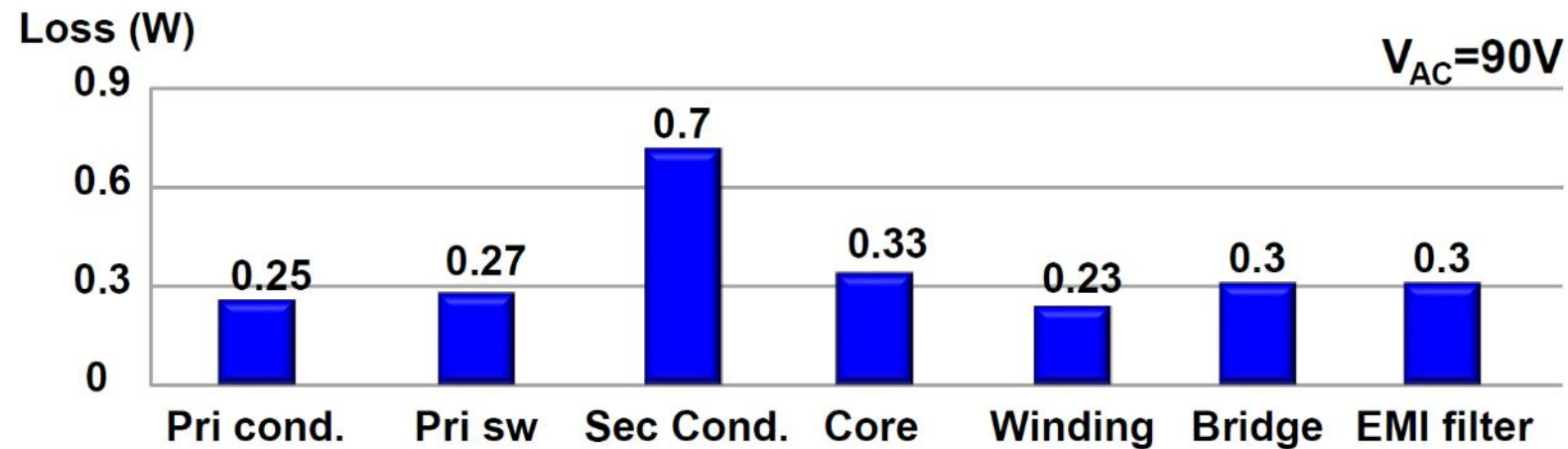
\* In-house EMI equipment

# ACF at 1MHz, 25W



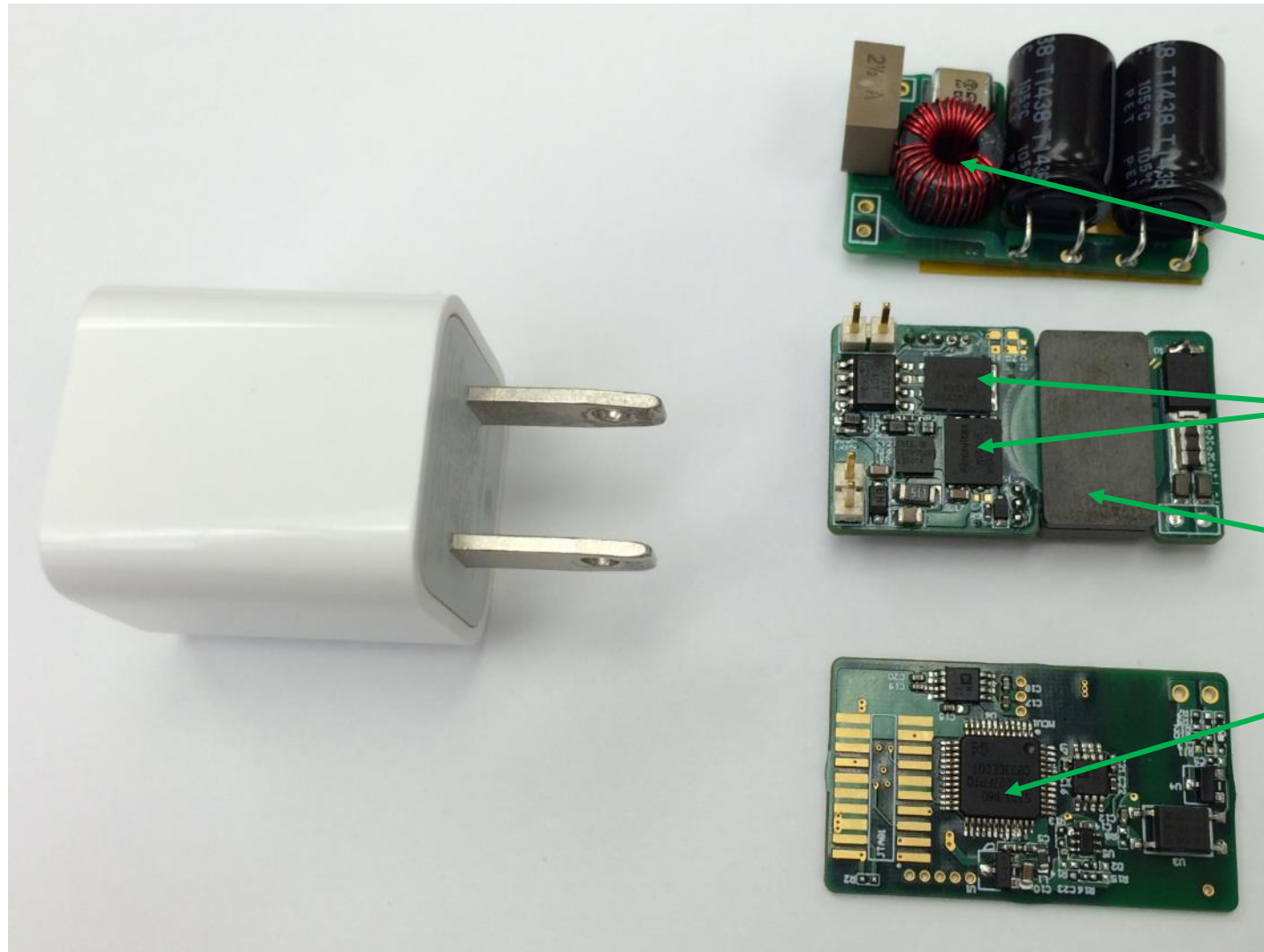
CPES Prototype  
25W

iPhone charger  
5W



**Eff  $\approx$  91.3% @  $P_o=25W$**

# 1MHz, 25W ACF



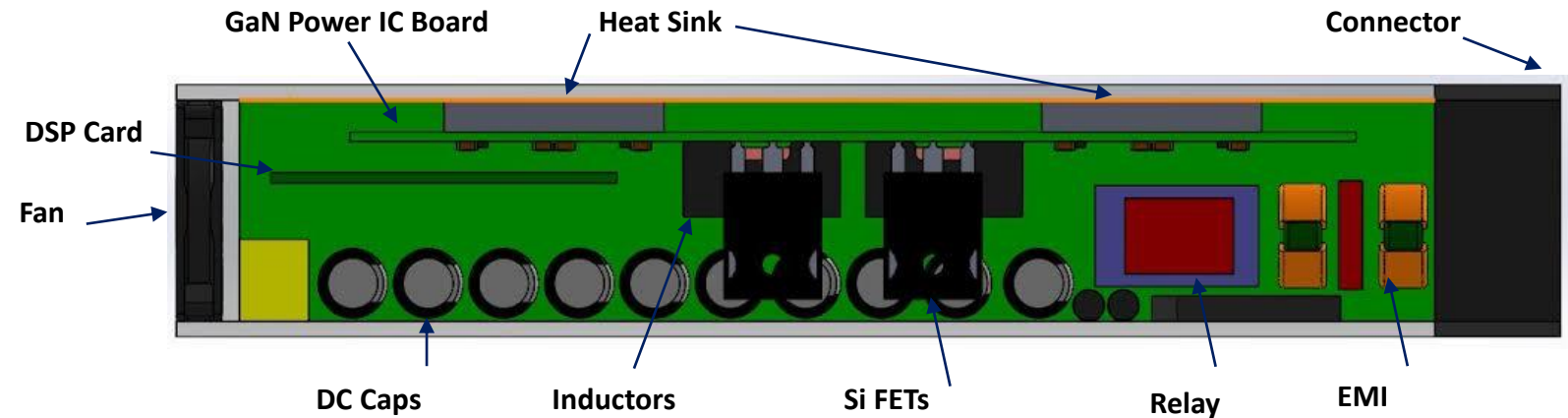
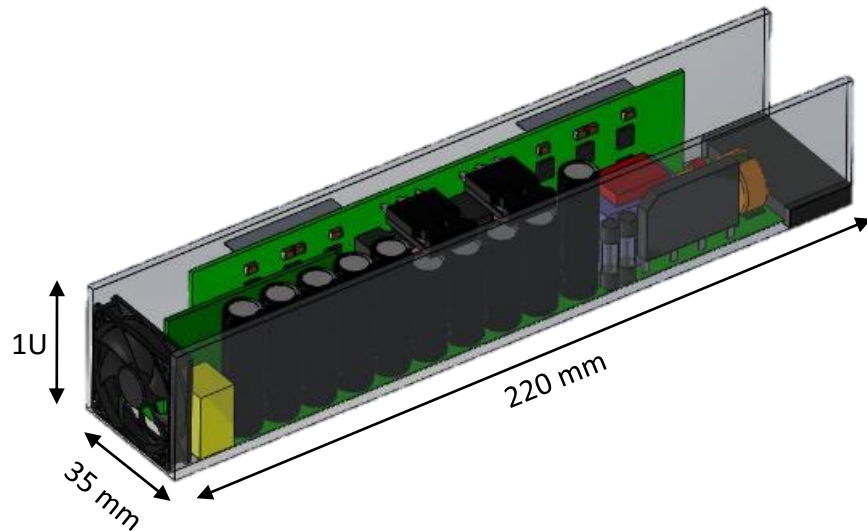
- Single-stage EMI
- Navitas GaN Power ICs
- Planar transformer
- DSP (for prototype)



# 1MHz 3kW PFC: 135W/in<sup>3</sup>

- 2-phase Totem-Pole CrCM
- Input : 220V<sub>AC</sub> (47-63Hz)
- Output : 400V, 3,000W

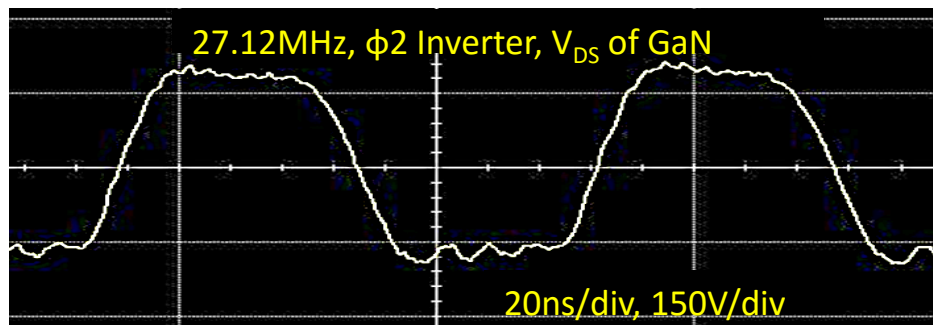
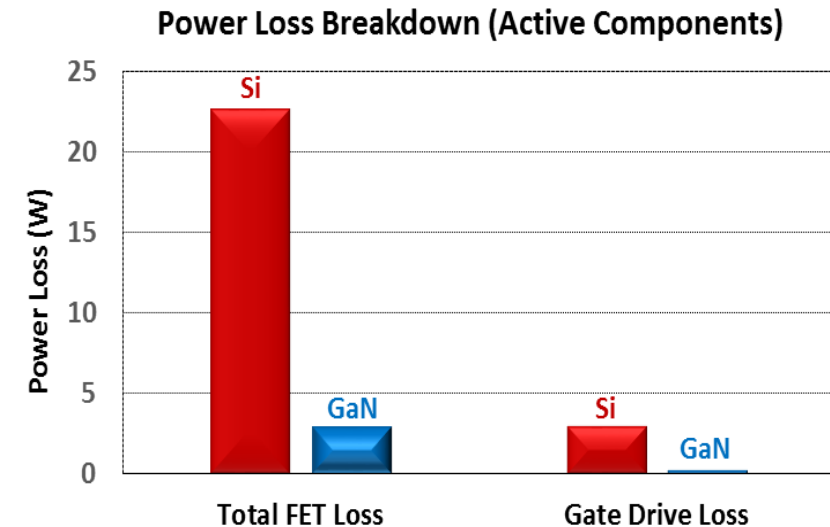
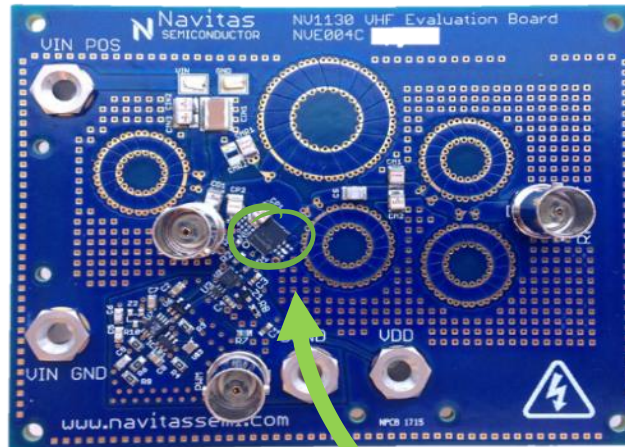
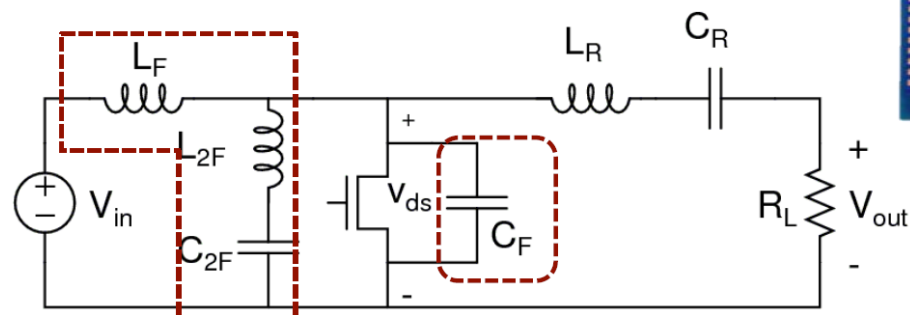
- Frequency\* : 1MHz each phase
  - \*Dual phase variable frequency interleaving (500kHz – 1.5MHz range)
- Efficiency : >99% @ 800kHz, 200-1,200W/phase <sup>(1)</sup>  
>98.8% @ 500kHz, 1,800W /phase <sup>(1)</sup>
- Power Factor : >0.995 <sup>(1)</sup>
- Power Density : 135W/in<sup>3</sup>



# eMode GaN at 27MHz & 40MHz

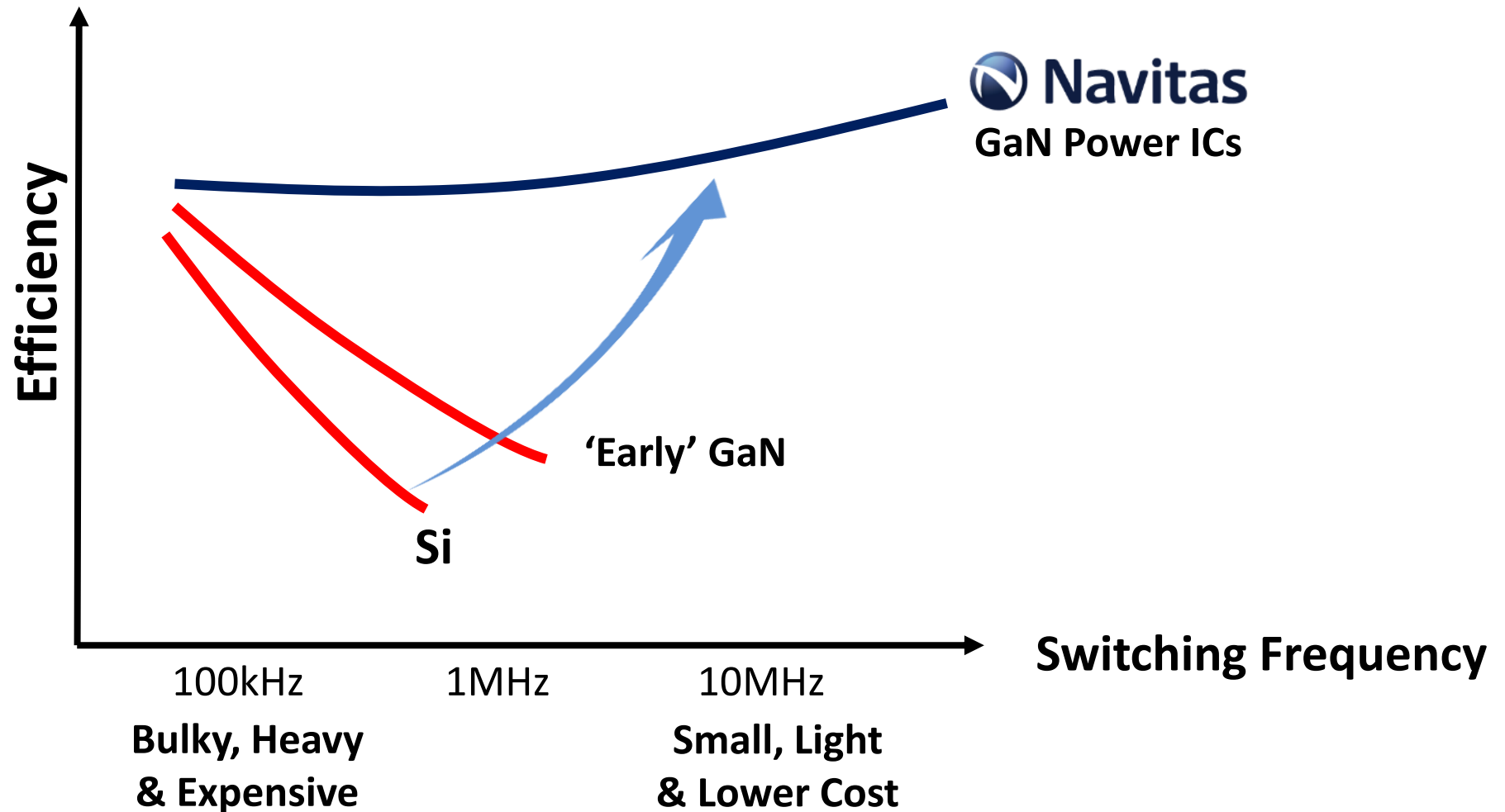
Class Phi-2 DC/AC converter: Stanford / Navitas demo

- 50% less loss than RF Si
- 16x smaller package
- Air-core inductors
- Minimal FET loss
- Negligible gate drive loss



Technology	V	Pack (mm)	$F_{sw}$ (MHz)	Eff. (%)	Power (W)
RF Si (ARF521) 	500	M174 22x22 	27.12	91%	150
eMode GaN 	650	QFN 5x6 	27.12	96%	150
			40.00	93%	115

# GaN Power ICs Enable High Frequency & Efficiency



## DRIVING FOR ZERO SWITCHING LOSS POWER SOLUTIONS

*Zero Loss!*  
*WIN, WIN, WIN*

